

HIGH-VOLTAGE MIXED-SIGNAL IC

UC1698

160 x 128RGB C-STN LCD Controller-Driver w/
16-bit per RGB On-Chip SRAM
Optimized for VSTN (Video-CSTN)

MP Specifications
Datasheet Revision: 1.7

IC Version: u_C
June 21, 2016

ULTRACHIP

The Coolest LCD Driver, Ever!!

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UC1698

*Single-Chip, 160COM x128RGB Matrix
Passive Color LCD Controller-Driver
with VSTN Support*

INTRODUCTION

UC1698u is an advanced high-voltage mixed-signal CMOS IC, specially designed for the display needs of low power hand-held devices.

In addition to low power COM and SEG drivers, UC1698u contains all necessary circuits for high-V LCD power supply, bias voltage generation, temperature compensation, timing generation, and graphics data memory.

UC1698u employs UltraChip's unique DCC (Direct Capacitor Coupling) driver architecture and LRM (Line Rate Modulation) gray-shade modulation scheme to achieve well balanced shading, vivid colors, and natural-looking images while supporting very fast Liquid Crystal material for video applications.

With UC1698u, LCD makers can now achieve TFT-like image quality, support video applications while maintaining the same STN advantages in power consumption, unit cost, ease of customization and production flexibility.

MAIN APPLICATIONS

- Cellular Phones and other battery-operated hand held devices or portable instruments

FEATURE HIGHLIGHTS

- Single chip controller-driver for 160x128 matrix C-STN LCD with comprehensive support for input format and color depth:

12-bit RGB:	4K-color
16-bit RGB:	64K-color
- Support monochrome STN and video rate CSTN applications.
- Window-write, window-skip functions to support flexible video applications such as OSD, dynamic service provider screen saver for cell phone and others.
- ID pin (ID1)-switched input data sets (D[7:0] or D[0, 2, 4, 6, 8, 10, 12, 14]) for 8-bit mode.
- One ID pin (ID0) plus two programmable ID flags, totally 4 software-readable ID bits to support configurable vendor identification.
- Partial scroll function and programmable data update window to support flexible manipulation of screen data.

- Supports both row-ordered and column-ordered display buffer RAM access.
- Supports industry standard 4-wire, 3/4-wire, and 3-wire serial buses (S8, S8uc, S9) and 16-bit/8-bit parallel buses (8080 or 6800).
- Special driver structure and gray shade modulation scheme. Low power consumption under all display patterns.
- No power consumption or image quality penalty when used with video rate CSTN.
- Fully programmable Mux Rate, partial display window, Bias Ratio and Line Rate allow many flexible power management options.
- Four software programmable temperature compensation coefficients.
- Software programmable, self-configuring 10x charge pump.
- Flexible data addressing/mapping schemes to support wide ranges of software models and LCD layout placements.
- Pad layouts support COG applications.
- V_{DD} (digital) range (typical): 1.8 V ~ 3.3V
 V_{DD} (analog) range (typical): 2.8 V ~ 3.3V
LCD V_{OP} range: 6.15V ~ 18V
- Allows Operating Temperature as low as -40°C (when VLCD is kept under 17.5V)
- Available MTP trimming supports precise LCD contrast matching.
- Available in gold bump dies.
- COM/SEG bump information
 - Bump pitch: 31 μM
 - Bump space: 13.5 μM
 - Bump surface: 2013 μM^2

Remark: Contact UltraChip for a visual inspection document (03-DOC-093).

ORDERING INFORMATION

GOLD BUMPED DIE

Part Number	MTP	I2C	Description
UC1698uGAC	Yes	No	Gold bumped die, with MTP function.
UC1698uGAC-2	Yes	No	Gold bumped die, with MTP function, Bump Height 12uM.
UC1698uGCC	Yes	No	Gold bumped die, with MTP function, Bump Height 15uM.
UC1698uGCC-2	Yes	No	Gold bumped die, with MTP function, Bump Height 12uM.

General Notes

APPLICATION INFORMATION

For improved readability, the specification contains many application data points. When application information is given, it is advisory and does not form part of the specification for the device.

BARE DIE DISCLAIMER

All die are tested and are guaranteed to comply with all data sheet limits up to the point of wafer sawing. There is no post waffle saw/pack testing performed on individual die. Although the latest processes are utilized for wafer sawing and die pick-&-place into waffle pack carriers, UltraChip has no control of third party procedures in the handling, packing or assembly of the die. Accordingly, it is the responsibility of the customer to test and qualify their applications in which the die is to be used. UltraChip assumes no liability for device functionality or performance of the die or systems after handling, packing or assembly of the die.

MTP LIGHT & ESD SENSITIVITY

The MTP memory cell is sensitive to photon excitation and ESD. Under extended exposure to strong ambient light, or when TST4 pin is exposed to ESD strikes, the MTP cells can lose its content before the specified memory retention time span. The system designer is advised to provide proper light & ESD shields to realize full MTP content retention performance.

LIFE SUPPORT APPLICATIONS

These devices are not designed for use in life support appliances, or systems where malfunction of these products can reasonably be expected to result in personal injuries. Customer using or selling these products for use in such applications do so at their own risk.

CONTENT DISCLAIMER

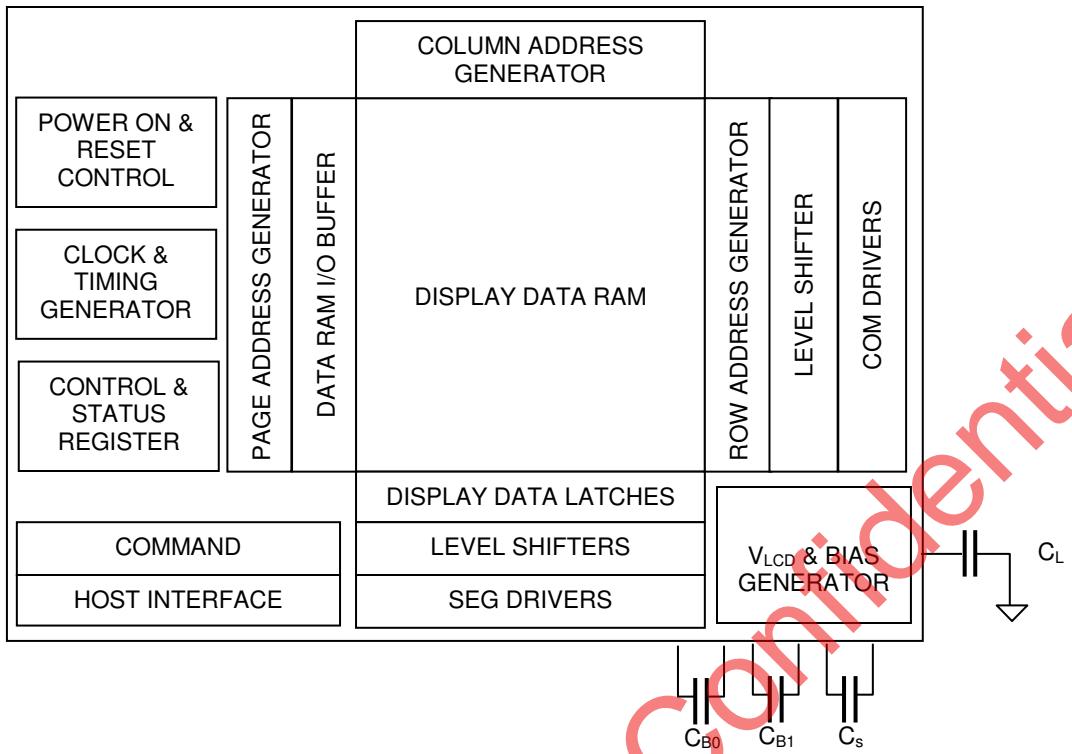
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CONTACT INFORMATION

UltraChip Inc. (Headquarter)
4F, No. 618, Recom Road,
Neihu District, Taipei 114,
Taiwan, R. O. C.

Tel: +886 (2) 8797-8947
Fax: +886 (2) 8797-8910
Sales e-mail: sales@ultrachip.com
Web site: http://www.ultrachip.com

BLOCK DIAGRAM



PIN DESCRIPTION

Pin Name (Pad Name)	Type	# of Pads	Description																																
MAIN POWER SUPPLY																																			
V _{DD} V _{DD2} V _{DD3}	PWR	9 9 2	<p>V_{DD} is the digital power supply and it should be connected to a voltage source that is no higher than V_{DD2}/V_{DD3}. V_{DD2}/V_{DD3} is the analog power supply and it should be connected to the same power source.</p> <p>Please maintain the following relationship: $V_{DD} + 1.3V \geq V_{DD2/3} \geq V_{DD}$</p> <p>Minimize the trace resistance for V_{DD} and V_{DD2}/V_{DD3}.</p>																																
V _{SS} V _{SS2}	GND	12 12	<p>Ground. Connect V_{SS} and V_{SS2} to the shared GND pin.</p> <p>Minimize the trace resistance for this node.</p>																																
LCD POWER SUPPLY & VOLTAGE CONTROL																																			
V _{B1+} , V _{B1-} V _{B0+} , V _{B0-} V _{S+} , V _{S-}	PWR	4, 4 4, 4 3, 3	<p>LCD SEG driving voltages. These are the voltage sources to provide SEG driving currents. These voltages are generated internally.</p> <p>Connect capacitors of C_{BX} value between V_{BX+} and V_{BX-}, and a capacitor of C_S value between V_{S+} and V_{S-}.</p> <p>The resistance of these traces directly affects the driving strength of SEG electrodes and impacts the image of the LCD module. Minimize the trace resistance is critical in achieving high quality image.</p>																																
V _{LCD-IN} V _{LCD-OUT}	PWR	2 2	<p>High voltage LCD Power Supply. When internal V_{LCD} is used, connect these pins together. When external V_{LCD} source is used, connect external V_{LCD} source to V_{LCDIN} pins and leave V_{LCDOUT} open.</p> <p>Capacitor C_L should be connected between V_{LCD} and V_{SS}. In COG applications, keep the ITO trace resistance around 20 Ω.</p>																																
NOTE: Recommended capacitor values:																																			
C _{BX} :	2.2μF/5V or 300x LCD load capacitance, whichever is higher.																																		
C _S :	150 ~ 220nF / 25V																																		
C _L :	330nF/25V is appropriate for most applications.																																		
HOST INTERFACE																																			
BM0 BM1 (BM<0> BM<1>)	I	1 1	<p>Bus mode: The interface bus mode is determined by BM[1:0] and {DB15, DB13} by the following relationship:</p> <table border="1"> <thead> <tr> <th>BM[1:0]</th> <th>{DB15, DB13}</th> <th>Mode</th> <th></th> </tr> </thead> <tbody> <tr> <td>11</td> <td>Data</td> <td>6800/16-bit</td> <td></td> </tr> <tr> <td>10</td> <td>Data</td> <td>8080/16-bit</td> <td></td> </tr> <tr> <td>01</td> <td>0x</td> <td>6800/8-bit</td> <td></td> </tr> <tr> <td>00</td> <td>0x</td> <td>8080/8-bit</td> <td></td> </tr> <tr> <td>00</td> <td>10</td> <td>4-wire SPI w/ 8-bit token</td> <td>(S8: conventional)</td> </tr> <tr> <td>00</td> <td>11</td> <td>3/4-wire SPI w/ 8-bit token</td> <td>(S8uc: Ultra-Compact)</td> </tr> <tr> <td>01</td> <td>10</td> <td>3-wire SPI w/ 9-bit token</td> <td>(S9: conventional)</td> </tr> </tbody> </table>	BM[1:0]	{DB15, DB13}	Mode		11	Data	6800/16-bit		10	Data	8080/16-bit		01	0x	6800/8-bit		00	0x	8080/8-bit		00	10	4-wire SPI w/ 8-bit token	(S8: conventional)	00	11	3/4-wire SPI w/ 8-bit token	(S8uc: Ultra-Compact)	01	10	3-wire SPI w/ 9-bit token	(S9: conventional)
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CS0 CS1 (CS<0> CS<1>)	I	1 1	Chip Select. Chip is selected when CS1="H" and CS0 = "L". When the chip is not selected, D[15:0] will be high impedance.																																
RST	I	1	<p>When RST="L", all control registers are re-initialized by their default states. Since UC1698u has built-in Power-ON reset and software reset commands, RST pin is not required for proper chip operation.</p> <p>An RC Filter has been included on-chip. There is no need for external RC noise filter. When RST is not used, connect the pin to V_{DD}.</p>																																

Pin Name (Pad Name)	Type	# of Pads	Description						
CD	I	1	Selects Control data or Display data for read/write operation. In S9 mode, CD pin is not used. Connect to V _{SS} when not used. "L": Control data "H": Display data						
ID0 (ID<0>)	I	1	ID0 pin can be used for production control. Connect ID0 pin to V _{DD} for "H" or V _{SS} for "L".						
ID1 (ID<1>)	I	1	Selects Input Data set for 8-bit mode. ID1=0 : 8-bit input data are D[0,2,4,6,8,10,12,14] ID1=1 : 8-bit input data are D[0:7] The wiring status of ID pins is available in PID[1:0] with command Get Status. Other than 8-bit mode, connect ID1 to V _{DD} for "H", or V _{SS} for "L".						
WR0 WR1 (WR<0> WR<1>)	I	1 1	WR[1:0] control the read/write operation of the host interface. See section <i>Host Interface</i> for more detail. In parallel mode, the meaning of WR[1:0] depends on whether the interface is in the 6800 mode or the 8080 mode. In serial interface modes, these two pins are not used, connect them to V _{SS} .						
DATA BUS									
D0~D15	I/O	16	Bi-directional bus for parallel host interfaces. In serial modes, connect DB[0] to SCK, DB[8] to SDA.						
				16-bit (BM=1x)	8-bit (BM=0x ID1=0)	8-bit (BM=0x ID1=1)	S8/S8uc (BM=00)		
			DB0	D0	D0/D8	D0/D8	SCK		
			DB1	D1	—	D1/D9	—		
			DB2	D2	D1/D9	D2/D10	—		
			DB3	D3	—	D3/D11	—		
			DB4	D4	D2/D10	D4/D12	—		
			DB5	D5	—	D5/D13	—		
			DB6	D6	D3/D11	D6/D14	—		
			DB7	D7	—	D7/D15	—		
			DB8	D8	D4/D12	—	SDA		
			DB9	D9	—	—	—		
			DB10	D10	D5/D13	—	—		
			DB11	D11	—	—	—		
			DB12	D12	D6/D14	—	—		
			DB13	D13	—	—	0:S8/1:S8uc		
			DB14	D14	D7/D15	—	0		
			DB15	D15	0	0	1		
Always connect unused pins to either V _{SS} or V _{DD} .									
HIGH VOLTAGE LCD DRIVER OUTPUT									
SEG1 ~ SEG384 (SEG<1>~ SEG<384>)	HV	384	SEG (column) driver outputs. Support up to 128xRGB pixels for CSTN display or 384 pixels for STN display. Leave unused SEG drivers open-circuit.						
COM1 ~ COM160 (COM<1>~ COM<160>)	HV	160	COM (row) driver outputs. Support up to 160 rows. When designing LCM, always start from COM1. If the LCM has N pixel rows and N is less than 160, set CEN to be N-1, and leave COM drivers [N+1 ~ 160] open-circuit.						

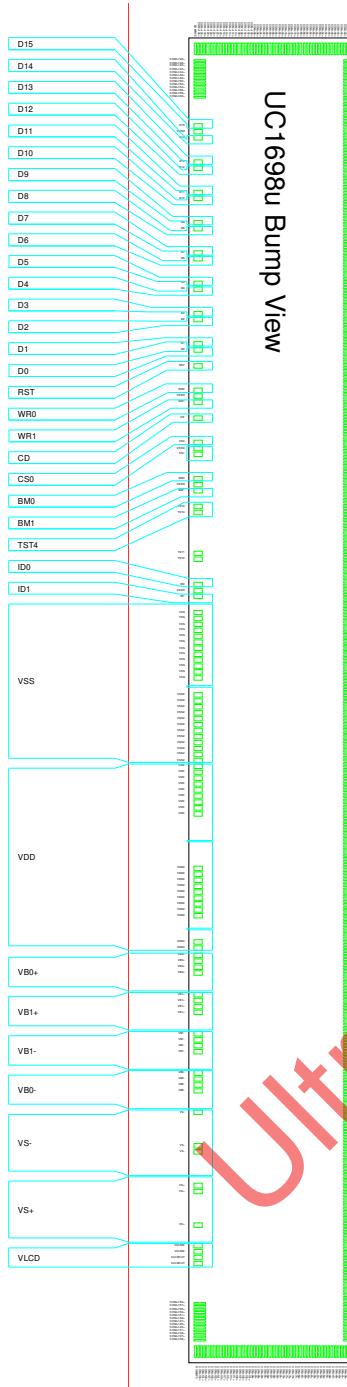
Pin Name (Pad Name)	Type	# of Pads	Description
MISC. PINS			
V _{DDX}	O	5	Auxiliary V _{DD} . These pins are connected to the main V _{DD} bus within the IC. These pads are provided to facilitate chip configurations in COG application. These pins should <u>NOT</u> be used to provide V _{DD} power to the chip. It is not necessary to connect V _{DDX} to main V _{DD} externally.
TST4	I/HV	2	Test control. This pin has on-chip pull-up resistor. Leave it open during normal operation. TST4 is also used as one of the high voltage power supply for MTP programming operation. For COG designs, please wire out TST4 with trace resistance between 30~50 Ω.
TST1 TST2	O	1 1	Test I/O pins. Leave these pins open during normal use.
Dummy, Dummy1~4		Ver.A --	Ver.C 41 1x4 Dummy pads.

NOTE:

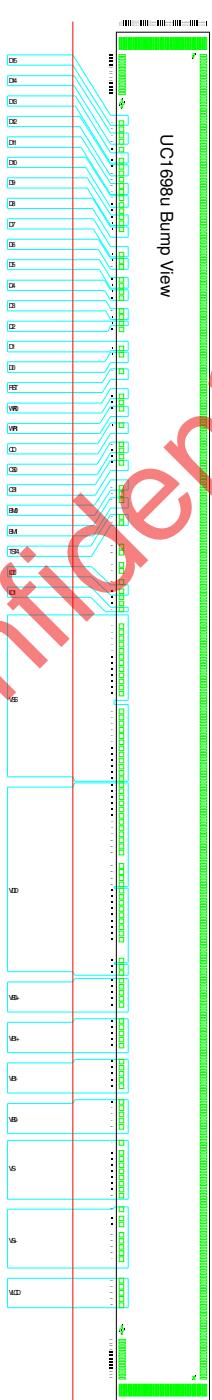
Several control registers will specify “0 based index” for COM and SEG electrodes. In those situations, COM_X or SEG_X will correspond to index X-1, and the value ranges for those index registers will be 0~159 for COM and 0~383 for SEG.

RECOMMENDED COG LAYOUT

For Part Number "UC1698ucGAC" and "UC1698ucGAC-2"



For Part Number "UC1698ucGCC" and "UC1698ucGCC-2"



Note for V_{DD} and V_{SS} with COG:

The operation condition $V_{DD} \geq 1.8V$ must be satisfied under all operating conditions. With its video capability, UC1698u peak current (I_{DD}) can be up to $\sim 15mA$ range during high speed data write to UC1698u's on-chip SRAM. Such high pulsing current mandates very careful design of V_{DD} , V_{SS} ITO trances in COG glass modules. When V_{DD} and V_{SS} trace resistance is not low enough, the pulsing I_{DD} current can cause the actual on-chip V_{DD} to drop below 1.65V and cause the IC to malfunction.

CONTROL REGISTERS

UC1698u contains registers which control the chip operation. The following table is a summary of these control registers, a brief description and the default values. These registers can be modified by commands, which will be described in the next two sections, starting with a summary table, followed by a detailed instruction-by-instruction description.

Name: The Symbolic reference of the register.

Note that, some symbol name refers to bits (flags) within another register.

Default: Numbers shown in **Bold** font are default values after *Power-Up-Reset* and *System-Reset*.

Name	Bits	Default	Description
SL	8	0H	Scroll Line. Scroll the displayed image up by SL rows. The valid SL value is between 0 (for no scrolling) and (159 – 2x(FLT+FLB)). Setting SL outside of this range causes undefined effect on the displayed image.
FLT FLB	4 4	0H 0H	Fixed Lines. The first FLT _x 2 lines and the last FLB _x 2 lines (relative to CEN) of each frame are fixed and are not affected by scrolling (SL). When FLT and/or FLB are non-zero, the screen is effectively separated into three regions: one scrollable, surrounded by two non-scrollable regions. When partial display mode is activated, the display of these 2xFLT and 2xFLB lines is also controlled by LC[0]. When LC[0]=1, the display will have three sections: 2xFLT on one side non-scrollable, 2xFLB on the other side also non-scrollable, and scrollable DST~DEN in the middle.
CA	7	0H	Display Data RAM Column Address (counted in RGB triplet) (Used in Host to Display Data RAM access)
RA	8	0H	Display Data RAM Row Address (Used in Host to Display Data RAM access)
BR	2	3H	Bias Ratio. The ratio between V _{LCD} and V _{BIAS} . 00b: 5 01b: 10 10b: 11 11b: 12
TC	2	0H	Temperature Compensation (per °C) 00b: -0.00% 01b: -0.05% 10b: -0.15% 11b: -0.25%
PM	8	40H	Electronic Potentiometer to fine tune V _{BIAS} and V _{LCD}
PMO	7	00H	PM offset. PMO[6]=1b: The effective PM value, PMV = PM - PMO[5:0] PMO[6]=0b: The effective PM value, PMV = PM + PMO[5:0]
PC	2	2H	Power Control. PC[0]: 0b: LCD ≤ 13nF 1b: 13nF < LCD ≤ 22nF PC[1]: 0b: External V _{LCD} 1b: Internal V _{LCD} (10x charge pump)
AC	4	1H	Address Control. AC[0]: WA: Automatic column/row Wraparound (Default 1 : ON) AC[1]: Auto-Increment order 0b : Column (CA) first 1b : Row (RA) first AC[2]: RID: RA (row address) Auto Increment Direction (L : +1 H : -1) AC[3] : Window Program Mode 0b : Inside Mode: Write to SRAM within the window defined by (WPC0,WPP0) and (WPC1,WPP1) 1b : Outside Mode: Write to SRAM but skip the window defined by (WPC0,WPP0) and (WPC1,WPP1)

Name	Bits	Default	Description																										
DC	5	18H	<p>Display Control:</p> <p>DC[0]: PVX: Pixels Inverse. Bit-wise data inversion. (Default 0: OFF)</p> <p>DC[1]: APO: All Pixels ON (Default 0: OFF)</p> <p>DC[2]: Display ON/OFF (Default 0: OFF)</p> <p>DC[3]: Gray-shade Modulation mode.</p> <p> 0 : On/Off mode 1 : 32-shade Mode</p> <p>DC[4]: Green Enhance Mode. <i>Only valid in 4K-color mode.</i></p> <p> 0 : Enable. Allows an extra display bit for green color. 1 : Disable</p>																										
LC	9	090H	<p>LCD Control:</p> <p>LC[0]: Enable the top FLTx2 and bottom FLBx2 lines in partial display mode (Default 0: OFF).</p> <p>LC[1]: MX, Mirror X. SEG/Column sequence inversion (Default: 0: OFF)</p> <p>LC[2]: MY, Mirror Y. COM/Row sequence inversion (Default: 0: OFF)</p> <p>LC[4:3]: Line Rate (Klps: Kilo-Line-per-second)</p> <table> <tr> <td>00b: 25.2. Klps</td> <td>01b: 30.5 Klps</td> </tr> <tr> <td>10b: 37.0 Klps</td> <td>11b: 44.8 Klps</td> </tr> </table> <p>Line Rate (for On/Off mode)</p> <table> <tr> <td>00b: 8.5 Klps</td> <td>01b: 10.4 Klps</td> </tr> <tr> <td>10b: 12.6 Klps</td> <td>11b: 15.2 Klps</td> </tr> </table> <p>(Line-Rate = Frame-Rate x Mux-Rate)</p> <p><u>for CSTN display:</u></p> <p>LC[5] : RGB filter order (as mapped to SEG1, SEG2, SEG3)</p> <table> <tr> <td>0 : BGR-BGR</td> <td>1 : RGB-RGB</td> </tr> </table> <p>LC[7:6] : Color and input mode</p> <table> <tr> <td>when DC[4]=1: 01b : 4K color mode.</td> <td>01b : 4K color mode.</td> </tr> <tr> <td></td> <td>10b : 64K color mode.</td> </tr> <tr> <td>when DC[4]=0: 01b : 4K color mode.</td> <td>01b : 4K color mode.</td> </tr> <tr> <td></td> <td>10b : 64K color mode.</td> </tr> </table> <p><u>for STN display:</u></p> <p>LC[5] : SEG filter order (as mapped to SEG1, SEG2, SEG3)</p> <table> <tr> <td>0b : Sn, Sn+1, Sn+2, ...</td> <td>1b : Sn+2, Sn+1, Sn, ...</td> </tr> </table> <p>LC[7:6] : Input mode</p> <table> <tr> <td>01b : 1 byte every 2 SEGs</td> <td>10b : 2 bytes every 3 SEGs</td> </tr> </table> <p>LC[8] : Partial Display Control</p> <table> <tr> <td>0b: Disable</td> <td>Mux-Rate = CEN+1 (DST, DEN not used)</td> </tr> <tr> <td>1b: Enabled</td> <td>Mux-Rate = DEN-DST+1+LC[0] x (FLT+FLB) x 2</td> </tr> </table>	00b: 25.2. Klps	01b: 30.5 Klps	10b: 37.0 Klps	11b: 44.8 Klps	00b: 8.5 Klps	01b: 10.4 Klps	10b: 12.6 Klps	11b: 15.2 Klps	0 : BGR-BGR	1 : RGB-RGB	when DC[4]=1: 01b : 4K color mode.	01b : 4K color mode.		10b : 64K color mode.	when DC[4]=0: 01b : 4K color mode.	01b : 4K color mode.		10b : 64K color mode.	0b : Sn, Sn+1, Sn+2, ...	1b : Sn+2, Sn+1, Sn, ...	01b : 1 byte every 2 SEGs	10b : 2 bytes every 3 SEGs	0b: Disable	Mux-Rate = CEN+1 (DST, DEN not used)	1b: Enabled	Mux-Rate = DEN-DST+1+LC[0] x (FLT+FLB) x 2
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NIV	5	1DH	<p>N-Line Inversion:</p> <table> <tr> <td>NIV[2:0]: 000b: 11 lines</td> <td>001b: 19 lines</td> </tr> <tr> <td>010b: 21 lines</td> <td>011b: 25 lines</td> </tr> <tr> <td>100b: 29 lines</td> <td>101b: 31 lines</td> </tr> <tr> <td>110b: 37 lines</td> <td>111b: 43 lines</td> </tr> </table> <p>NIV[3]: 0b: no-XOR</p> <p>NIV[4]: 0b: Disable NIV</p> <p>1b: XOR</p> <p>1b: Enable NIV</p>	NIV[2:0]: 000b: 11 lines	001b: 19 lines	010b: 21 lines	011b: 25 lines	100b: 29 lines	101b: 31 lines	110b: 37 lines	111b: 43 lines																		
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100b: 29 lines	101b: 31 lines																												
110b: 37 lines	111b: 43 lines																												
CSF	3	0H	<p>COM Scan Function</p> <p>CSF[0]: Interlace Scan Function</p> <table> <tr> <td>0b: LRM sequence: AEBCD-AEBCD</td> <td>1b: LRM sequence: AEBCD-EBCDA</td> </tr> </table> <p>CSF[1]: FRC function</p> <table> <tr> <td>0: Disable FRC</td> <td>1: Enable FRC</td> </tr> </table> <p>CSF[2]: Shade-1 / Shade-30 option</p> <table> <tr> <td>0: Dither directly on input data (SRAM Change)</td> <td>1: PWM (Pulse-width modulation) on SEG output stage</td> </tr> </table>	0b: LRM sequence: AEBCD-AEBCD	1b: LRM sequence: AEBCD-EBCDA	0: Disable FRC	1: Enable FRC	0: Dither directly on input data (SRAM Change)	1: PWM (Pulse-width modulation) on SEG output stage																				
0b: LRM sequence: AEBCD-AEBCD	1b: LRM sequence: AEBCD-EBCDA																												
0: Disable FRC	1: Enable FRC																												
0: Dither directly on input data (SRAM Change)	1: PWM (Pulse-width modulation) on SEG output stage																												

Name	Bits	Default	Description
CEN	8	9FH	COM scanning end (last COM with full line cycle, 0 based index)
DST	8	00H	Display start (first COM with active scan pulse, 0 based index)
DEN	8	9FH	Display end (last COM with active scan pulse, 0 based index) Please maintain the following relationship: CEN = the actual number of pixel rows on the LCD - 1 CEN ≥ DEN ≥ DST+ 9
WPC0	7	00H	Window program starting column address. Value range: 0 ~127.
WPP0	8	00H	Window program starting row address. Value range: 0~159.
WPC1	7	7FH	Window program ending column address. Value range: 0~127.
WPP1	8	9FH	Window program ending row address. Value range: 0~159
MTPC	5	10H	MTP Programming Control: MTPC[2:0] : MTP command 000 : Idle 001 : Read 010 : Erase 011 : Program 1xx : For UltraChip's debug use only MTPC[3] : MTP Enable (automatically cleared after each MTP command) MTPC[4] : Ignore/Use MTP. 0: Ignore 1: Use
MTP	7	--	Multiple-Time Programming. For V _{LCD} fine tune.
MTPID	2	--	Multiple-Time Programming. For LCM manufacturer's configuration.
MTPM	7	00H	MTP Write Mask. Bit =1: program, Bit=0: no action.
MTPM1	2	0H	MTP Write Mask. Bit =1: program, Bit=0: no action.
APC		N/A	Advanced Program Control. For UltraChip only. Please do not use.
Status Registers			
OM	2	-	Operating Modes (Read only) 00b: Reset 01b: (Not used) 10b: Sleep 11b: Normal
MD	1	-	MTP option flag: 1 for MTP version, 0 for non-MTP version.
MS	1	-	MTP programming in-progress
WS	1	-	MTP Operation Succeeded
ID	2	PIN	Access the connected status of ID pins.

COMMAND TABLE

The following is a list of host commands supported by UC1698u

C/D : 0: Control, 1: Data

W/R : 0: Write Cycle, 1: Read Cycle

D7-D0 : # : Useful Data bits – : Don't Care

#	Command	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Action	Default		
1	Write Data Byte	1	0	#	#	#	#	#	#	#	#	Write 1 byte	N/A		
2	Read Data Byte	1	1	#	#	#	#	#	#	#	#	Read 1 byte	N/A		
3	Get Status & PM	0	1	GE	MX	MY	WA	DE	WS	MD	MS	Get {Status, Ver, PMO, Product Code, PID, MID}	Product Code: 8h		
				Ver	PMO[6:0]										
				Product Code			PID[1:0]		MID[1:0]						
4	Set Column Address LSB	0	0	0	0	0	0	#	#	#	#	Set CA[3:0]	0		
	Set Column Address MSB	0	0	0	0	0	1	0	#	#	#	Set CA[6:4]	0		
5	Set Temp. Compensation	0	0	0	0	1	0	0	1	#	#	Set TC[1:0]	0		
6	Set Power Control	0	0	0	0	1	0	1	0	#	#	Set PC[1:0]	10b		
7	Set Adv. Program Control (double-byte command)	0	0	0	0	1	1	0	0	0	R	Set APC[R][7:0], R = 0 or 1	N/A		
				#	#	#	#	#	#	#	#				
8	Set Scroll Line LSB	0	0	0	1	0	0	#	#	#	#	Set SL[3:0]	0		
	Set Scroll Line MSB	0	0	0	1	0	1	#	#	#	#	Set SL[7:4]	0		
9	Set Row Address LSB	0	0	0	1	1	0	#	#	#	#	Set RA[3:0]	0		
	Set Row Address MSB	0	0	0	1	1	1	#	#	#	#	Set RA[7:4]	0		
10	Set V _{BIAS} Potentiometer (double-byte command)	0	0	1	0	0	0	0	0	0	1	Set PM[7:0]	40H		
		0	0	#	#	#	#	#	#	#	#				
11	Set Partial Display Control	0	0	1	0	0	0	0	1	0	#	Set LC[8]	0		
	Set RAM Address Control	0	0	1	0	0	0	0	1	#	#	Set AC[2:0]	001b		
13	Set Fixed Lines	0	0	1	0	0	1	0	0	0	0	Set {FLT, FLB}	0		
		0	0	#	#	#	#	#	#	#	#				
14	Set Line Rate	0	0	1	0	1	0	0	0	#	#	Set LC[4:3]	10b		
15	Set All-Pixel-ON	0	0	1	0	1	0	0	1	0	#	Set DC[1]	0		
16	Set Inverse Display	0	0	1	0	1	0	0	1	1	#	Set DC[0]	0		
17	Set Display Enable	0	0	1	0	1	0	1	#	#	#	Set DC[4:2]	110b		
18	Set LCD Mapping Control	0	0	1	1	0	0	0	#	#	#	Set LC[2:0]	0		
19	Set N-Line Inversion	0	0	1	1	0	0	1	0	0	0	Set NIV[4:0]	1DH		
20	Set Color Pattern	0	0	1	1	0	1	0	0	0	#	Set LC[5]	0 (BGR)		
21	Set Color Mode	0	0	1	1	0	1	0	1	#	#	Set LC[7:6]	10b		
22	Set COM Scan Function	0	0	1	1	0	1	1	#	#	#	Set CSF[2:0]	000b		
23	System Reset	0	0	1	1	1	0	0	0	1	0	System Reset	N/A		
24	NOP	0	0	1	1	1	0	0	0	0	1	No operation	N/A		
25	Set Test Control (double-byte command)	0	0	1	1	1	0	0	1	TT		For testing only. Do not use.	N/A		
		0	0	#	#	#	#	#	#	#	#				
26	Set LCD Bias Ratio	0	0	1	1	1	0	1	0	#	#	Set BR[1:0]	11b: 12		
27	Set COM End	0	0	1	1	1	1	0	0	0	1	Set CEN[6:0]	159		
		0	0	-	#	#	#	#	#	#	#				
28	Set Partial Display Start	0	0	1	1	1	1	1	0	0	1	Set DST[6:0]	0		
		0	0	-	#	#	#	#	#	#	#				
29	Set Partial Display End	0	0	1	1	1	1	1	0	0	1	Set DEN[6:0]	159		
		0	0	-	#	#	#	#	#	#	#				
30	Set Window Program Starting Column Address	0	0	1	1	1	1	1	0	1	0	Set WPC0	0		
		0	0	-	#	#	#	#	#	#	#				
31	Set Window Program Starting Row Address	0	0	1	1	1	1	1	0	1	0	Set WPP0	0		
		0	0	#	#	#	#	#	#	#	#				
32	Set Window Program Ending Column Address	0	0	1	1	1	1	1	0	1	1	Set WPC1	127		
		0	0	-	#	#	#	#	#	#	#				
33	Set Window Program Ending Row Address	0	0	1	1	1	1	1	0	1	1	Set WPP1	159		
		0	0	#	#	#	#	#	#	#	#				
34	Window Program Mode	0	0	1	1	1	1	1	1	0	0	Set AC[3]	0: Inside		
35	Set MTP Operation control	0	0	1	0	1	1	1	0	0	0	Set MTPC[4:0]	10H		
		0	0	-	-	-	#	#	#	#	#				

#	Command	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Action	Default
36	Set MTP Write Mask	0 0 0	0 0 0	1 -	0 # -	1 # -	1 # -	1 # -	0 # -	0 # -	1 # #	Set MTPM[6:0] MTPM1[1:0]	0
37	Set V _{MTP1} Potentiometer	0 0	0 #	1 #	1 #	1 #	1 #	0 #	1 #	0 #	0 #	Set MTP1	N/A
38	Set V _{MTP2} Potentiometer	0 0	0 #	1 #	1 #	1 #	1 #	0 #	1 #	0 #	1 #	Set MTP2	N/A
39	Set MTP Write Timer	0 0	0 #	1 #	1 #	1 #	1 #	0 #	1 #	1 #	0 #	Set MTP3	N/A
40	Set MTP Read Timer	0 0	0 #	1 #	1 #	1 #	1 #	0 #	1 #	1 #	1 #	Set MTP4	N/A

NOTE:

- All other bit patterns other than commands listed above may result in undefined behavior.
- The interpretation of commands (36)~(40) depends on the setting of register MTPC[3].
 - Commands (37)~(40) are shared with commands (30)~(33). These two sets of commands share exactly the same code and control registers. When MTPC[3]=0, they are interpreted as Window Program commands and registers. When MTPC[3]=1, they function as MTP Control commands and registers.
- After MTP ERASE or PROGRAM operation, before resuming normal operation, please always
 - a) Remove TST4 power source,
 - b) Do a full V_{DD} ON-OFF-ON cycle.
- Under 16-bit bus mode and CD=0, D[15:8] is ignored and only D[7:0] is used. As a result, the bus cycles for commands under 16-bit bus and 8-bit bus are the same, and double-byte commands still need two bus cycles under 16-bit bus mode.

Example:

8-bit bus mode:

```
Set PL[1:0] = 2'b11 :    D[7:0] = 0010 1011
Set PM[7:0] = 8'h8b : 1st D[7:0] = 1000 0001
                           2nd D[7:0] = 1000 1011
```

16-bit bus mode:

```
Set PL[1:0] = 2'b11:   D[15:0] = 0000 0000  0010 1011
Set PM[7:0] = 8'h8b: 1st D[15:0] = 0000 0000  1000 0001
                           2nd D[15:0] = 0000 0000  1000 1011
```

COMMAND DESCRIPTION

(1) WRITE DATA TO DISPLAY MEMORY

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Write data	1	0								

UC1698u will convert input RAM data to 16-bit of RGB data. Please refer to command *Set Color Mode* for detail of data-write sequence.

(2) READ DATA FROM DISPLAY MEMORY

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Read data	1	1								

Each RGB triplet is stored as 16-bit in the display RAM. Each 16-bit of RGB data takes 1 (/ 2) RAM read cycles for 16 (/ 8) -bit bus mode, respectively. The read out RGB data is *after-extension* for 64K color mode.

R4	R3	R2	R1	R0	G5	G4	G3	G2	G1	G0	B4	B3	B2	B1	B0
1 st 8-bit Read								2 nd 8-bit Read							

For Black-and-White

Sn	-	-	-	-	Sn+1	-	-	-	-	Sn+2	-	-	-	-	-
1 st 8-bit Read								2 nd 8-bit Read							

Write/Read Data Byte (commands (1) and (2)) operation uses internal Row Address register (RA) and Column Address register (CA). RA and CA can be programmed by issuing commands *Set Row Address* and *Set Column Address*. If wrap-around (WA, AC[0]) is OFF (0), CA will stop incrementing after reaching the CA boundary, and system programmers need to set the values of RA and CA explicitly. If WA is ON (1), when CA reaches end of column address, CA will be reset to 0 and RA will be increased or decreased, depending on the setting of Row Increment Direction (RID, AC[2]). When RA reaches the boundary of RAM (i.e. RA = 0 or 127), RA will be wrapped around to the other end of RAM and continue.

For 8-bit / 16-bit interface, the first 1 byte / 2 bytes of read, respectively, is a dummy read. Please ignore the data read out.

(3) GET STATUS & PM

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	
Get Status	0	1	GE	MX	MY	WA	DE	WS	MD	MS	
	0	1	Ver				PMO[6:0]				
	0	1		Product Code					PID[1:0]	MID[1:0]	

Status1 definitions:

GE : Green Enhancing enable flag. Green Enhance Mode is disabled when GE = 1.

MX : Status of register LC[1], mirror X.

MY : Status of register LC[2], mirror Y.

WA : Status of register AC[0]. Automatic column/row wrap around.

DE : Display enable flag. DE=1 when display is enabled

WS : MTP Operation succeeded

MD : MTP Option (1 for MTP version, 0 for non-MTP version)

MS : MTP action status

Status2 definitions:

Ver : IC Version Code. 0 or 1.

PMO[6:0] : PM offset value.

Status3 definitions:

Product Code : 1000b (8h)

PID[1:0] : Provide access to ID pins connection status.

MID[1:0] : LCM manufacturer's configuration.

If multiple Get Status commands are issued consecutively within one single CD 1⇒0⇒1 transaction, the Get Status command will return {Status1, Status2, Status3, Status1, Status2, Status3, Status1..} alternately.

(4) SET COLUMN ADDRESS

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Column Address LSB CA[3:0]	0	0	0	0	0	0	CA3	CA2	CA1	CA0
Set Column Address MSB CA[7:4]	0	0	0	0	0	1	0	CA6	CA5	CA4

Set SRAM column address for read/write access. CA is counted in RGB triplets, not individual SEG electrode.

CA value range: 0~127

(5) SET TEMPERATURE COMPENSATION

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Temperature Comp. TC[1:0]	0	0	0	0	1	0	0	1	TC1	TC0

Set V_{BIAS} temperature compensation coefficient (%-per-degree-C)

Temperature compensation curve definition:

00b = -0.00%/ $^{\circ}$ C

01b = -0.05%/ $^{\circ}$ C

10b = -0.15%/ $^{\circ}$ C

11b = -0.25%/ $^{\circ}$ C

(6) SET POWER CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Panel Loading PC[1:0]	0	0	0	0	1	0	1	0	PC1	PC0

Set PC[0] according to the capacitance loading of LCD panel.

Panel loading definition: **0b : LCD \leq 13nF** **1b : 13nF < LCD \leq 22nF**

Set PC[1] to program the build-in charge pump stages. Before changing PC[1] value, always ensure the IC is in a RESET state. Avoid changing PC[1] when the display is enabled.

Pump control definition: **0b = External V_{LCD}** **1b = Internal V_{LCD} (x10)**

(7) SET ADVANCED PROGRAM CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set APC[R][7:0] (Double-byte command)	0	0	0	0	1	1	0	0	0	R
	0	0								APC register parameter

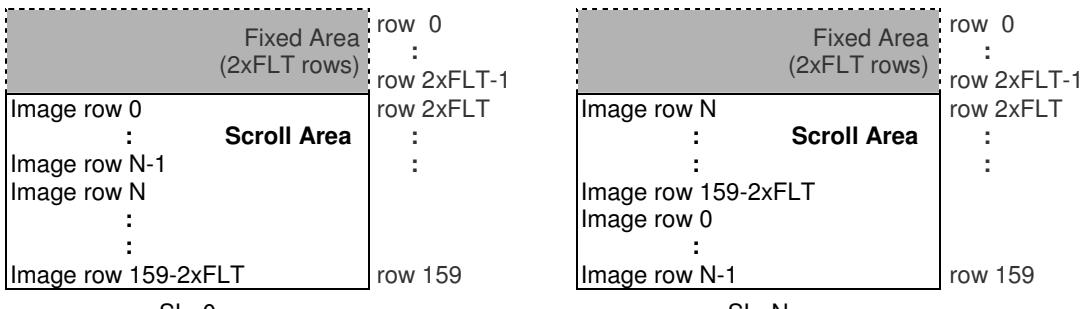
For UltraChip only. Please do NOT use.

(8) SET SCROLL LINE

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Scroll Line LSB SL[3:0]	0	0	0	1	0	0	SL3	SL2	SL1	SL0
Set Scroll Line MSB SL[7:4]	0	0	0	1	0	1	SL7	SL6	SL5	SL4

Set the scroll line number.

Scroll line setting will scroll the displayed image up by SL rows. The valid value for SL is between 0 (no scrolling) and 159-2x(FLT+FLB) (full scrolling). FLT and FLB are the register values programmed by the Set Fixed Lines command.



SL=0

SL=N

(9) SET ROW ADDRESS

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Row Address LSB RA [3:0]	0	0	0	1	1	0	RA3	RA2	RA1	RA0
Set Row Address MSB RA [7:4]	0	0	0	1	1	1	RA7	RA6	RA5	RA4

Set SRAM row address for read/write access.

Possible value = 0~159

(10) SET V_{BIAST} POTENTIOMETER

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set V _{BIAST} Potentiometer. PM [7:0] (Double-byte command)	0	0	1	0	0	0	0	0	0	1
	0	0	PM7	PM6	PM5	PM4	PM3	PM2	PM1	PM0

Program V_{BIAST} Potentiometer (PM[7:0]). See section *LCD Voltage Setting* for more detail.

Effective range: 0 ~ 255

(11) SET PARTIAL DISPLAY CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Partial Display Enable LC[8]	0	0	1	0	0	0	0	1	0	LC8

This command is used to enable partial display function.

LC[8] : 0b: Disable Partial Display, Mux-Rate = CEN+1 (DST, DEN not used.)
1b: Enable Partial Display, Mux-Rate = DEN-DST+1+ LC[0]x(FLT+FLB)x2

(12) SET RAM ADDRESS CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set AC [2:0]	0	0	1	0	0	0	1	AC2	AC1	AC0

Program registers AC[2:0] for RAM address control.

AC[0]: WA, Automatic column/row wrap around.

0: CA or RA (depends on AC[1]= 0 or 1) will stop incrementing after reaching boundary

1: CA or RA (depends on AC[1]= 0 or 1) will restart, and RA or CA will increment by one step.

AC[1]: Auto-Increment order

0 : column (CA) increment (+1) first until CA reaches CA boundary, then RA will increment by (+/-1).

1 : row (RA) increment (+/-1) first until RA reach RA boundary, then CA will increment by (+1).

AC[2]: RID, row address (RA) auto increment direction (0/1 = +/- 1)

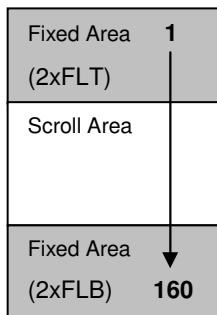
When WA=1 and CA reaches CA boundary, RID controls whether row address will be adjusted by +1 or -1.

AC[2:0] controls the auto-increment behavior of CA and RA. For Window Program mode (AC[3]=ON), see section *Command Description* (32) ~ (35) for more details. If WPC[1:0] and WPP[1:0] values are the default values, the behavior of CA, RA auto-increment will be the same, no matter what the setting of AC[3] is.

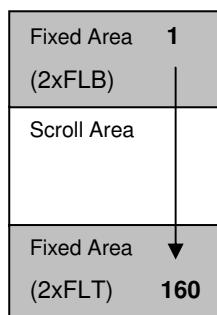
(13) SET FIXED LINES

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Fixed Lines {FLT,FLB}	0	0	1	0	0	1	0	0	0	0
(Double-byte command)	0	0		FLT[3:0]				FLB[3:0]		

The fixed line function is used to implement the partial scroll function by dividing the screen into scroll and fixed area. The Set Fixed Lines command will define the fixed area, which will not be affected by the SL scroll function. The fixed area covers the top 2xFLT and bottom 2xFLB rows for mirror Y (MY) is 0, or covers the top 2xFLB and bottom 2xFLT rows for MY=1. One example of the visual effect on LCD is illustrated in the figure below.



MY = 0



MY = 1

When partial display mode is activated, the display of these 2x(FLT+FLB) lines is also controlled by LC[0]. Before turning on LC[0], ensure:

MY=0 DST \geq FLT_{x2}
DEN \leq (CEN-FLB_{x2}).

MY=1 DST \geq FLB_{x2}
DEN \leq (CEN-FLT_{x2})

(14) SET LINE RATE

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Line Rate LC [4:3]	0	0	1	0	1	0	0	0	LC4	LC3

Program LC [4:3] for line rate setting (Frame-Rate = Line-Rate / Mux-Rate). The line rate is automatically scaled down by 2/3, 1/2, 1/3 and 1/4 at Mux-Rate = 108, 80, 56, and 40.

The following are line rates at Mux Rate = 109 ~ 160.

00b: 25.2 Klps

01b: 30.5 Klps

10b: 37.0 Klps

11b: 44.8 Klps

In On/Off Mode

00b: 8.5 Klps

01b: 10.4 Klps

10b: 12.6 Klps

11b: 15.2 Klps

(Klps: Kilo-Line-per-second)

(15) SET ALL PIXEL ON

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set All Pixel ON DC [1]	0	0	1	0	1	0	0	1	0	DC1

Set DC[1] to force all SEG drivers to output ON signals. This function has no effect on the existing data stored in display RAM.

(16) SET INVERSE DISPLAY

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Inverse Display DC [0]	0	0	1	0	1	0	0	1	1	DC0

Set DC[0] to force all SEG drivers to output the inverse of the data (bit-wise) stored in display RAM. This function has no effect on the existing data stored in display RAM.

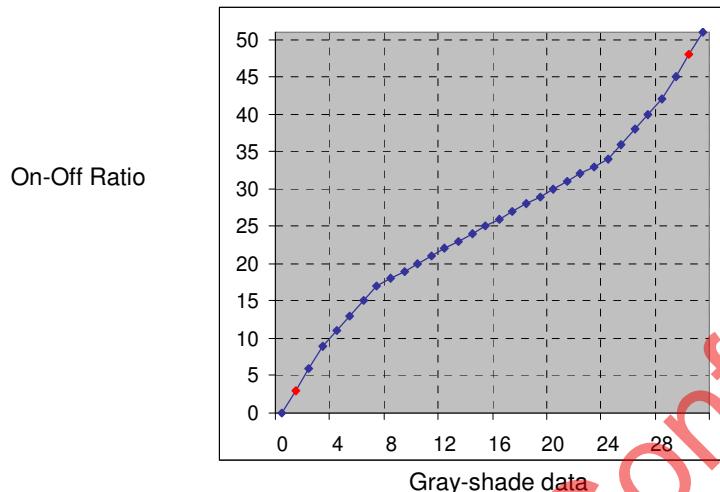
(17) SET DISPLAY ENABLE

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Display Enable DC [4:2]	0	0	1	0	1	0	1	DC4	DC3	DC2

This command is for programming register DC[4:2].

When DC[2] is set to 0, the IC will put itself into Sleep mode. All drivers, voltage generation circuit and timing circuit will be halted to conserve power. When DC[2] is set to 1, UC1698u will first exit from Sleep mode, restore the power and then turn on COM drivers and SEG drivers. There is no other explicit user action or timing sequence required to enter or exit the Sleep mode.

DC[3] controls the gray shade modulation modes. UC1698u has two gray shade modulation modes: an On/Off mode and a 32-shade mode. The modulation curves are shown below. Horizontal axes are the gray shade data. The vertical axes are the ON-OFF ratio.



DC[4] Green Enhance Mode. Refer to command Set Color Mode for more information.

0b: Green Enhancing Mode enabled **1b: Green Enhancing Mode disabled**

NOTE:

- For red and blue colors, when PWM is off, the shades mapped to data 1 and 30 (shown as red points above) are achieved by special dithering. When PWM is on, these shades are produced by PWM.
- Green shades are created by combining FRC (default: Off) and special dithering. When PWM is off, six of the shades (1, 2, 3, 59, 60, and 61) are created by special dithering while they are created by PWM when PWM is on. Data 62 and 63 are mapped to the same shade.
- When the internal DC-DC converter starts to operate and pump out current to V_{LCD} , there will be an in-rush pulse current between V_{DD2} and V_{SS2} initially. To avoid this current pulse from causing potential harmful noise, do NOT issue any command or write any data to UC1698u for 5~10mS after setting DC[2] to 1.

(18) SET LCD MAPPING CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set LCD Mapping Control LC [2:0]	0	0	1	1	0	0	0	MY	MX	LC0

This command is used for programming LC[2:0] to control COM (row) mirror (MY), SEG (column) mirror (MX).

LC[2] controls Mirror Y (MY): MY is implemented by reversing the mapping order between RAM and COM electrodes. The data stored in RAM is not affected by the MY action. MY will have immediate effect on the display image.

LC[1] controls Mirror X (MX): MX is implemented by selecting the CA or 127-CA as write/read (from host interface) display RAM column address so this function will only take effect after rewriting the RAM data.

LC[0] controls whether soft icon sections (2xFLT, 2xFLB) are displayed during partial display mode.

(19) SET N-LINE INVERSION

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set N-line inversion NIV[3:0]	0	0	1	1	0	0	1	0	0	0
(Double-byte command)	0	0	-	-	-	NIV4	NIV3	NIV2	NIV1	NIV0

N-Line Inversion:

NIV[2:0]: 000b: 11 lines
100b: 29 lines

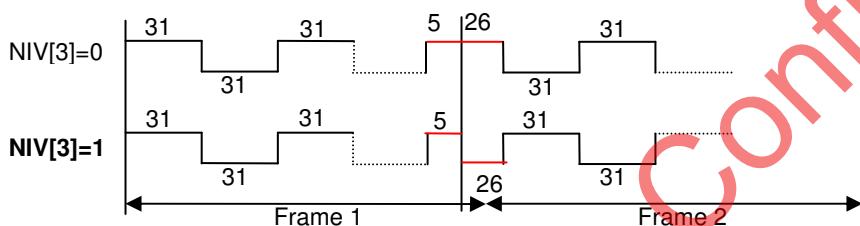
001b: 19 lines
101b: 31 lines

010b: 21 lines
110b: 37 lines

011b: 25 lines
111b: 43 lines

NIV[3]: 0b: non-XOR
NIV[4]: 0b: Disable NIV

1b: XOR
1b: Enable NIV



(20) SET COLOR PATTERN

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Color Pattern LC [5]	0	0	1	1	0	1	0	0	0	LC5

UC1698u supports on-chip swapping of R↔B data mapping to the SEG drivers.

LC[5]	SEG1	SEG2	SEG3	SEG4	SEG5	SEG6	...	SEG382	SEG383	SEG384
0	B	G	R	B	G	R	...	B	G	R
1	R	G	B	R	G	B	...	R	G	B

The definition of R/G/B input data is determined by LC[7:6], as described in Set Color Mode below.

For STN display:

LC[5]	SEG1	SEG2	SEG3	SEG4	SEG5	SEG6	...	SEG382	SEG383	SEG384
0	Sn+2	Sn+1	Sn	Sn+2	Sn+1	Sn	...	Sn+2	Sn+1	Sn
1	Sn	Sn+1	Sn+2	Sn	Sn+1	Sn+2	...	Sn	Sn+1	Sn+2

(21) SET COLOR MODE

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Color Mode LC [7:6]	0	0	1	1	0	1	0	1	LC7	LC6

Program color mode and RGB input pattern. Color mode (LC[7:6]) definition:

Note: For serial bus modes, please refer to 8-bit tables below.

Green Enhance Mode disabled (DC[4]=1):

LC[7:6] = 01b (RRRR-GGGG-BBBB, 4K-color)

12 bits of input RGB data are stored to 16 RAM bits. No dither is performed. Every 3 bytes of input data will be merged into 2 sets of RGB data.

Data Write Sequence (8-bit)	D[7:0]
1 st Write Data Cycle	R3 R2 R1 R0 G3 G2 G1 G0
2 nd Write Data Cycle	B3 B2 B1 B0 R3 R2 R1 R0
3 rd Write Data Cycle	G3 G2 G1 G0 B3 B2 B1 B0

Data Write Sequence (16-bit)	D[15:0]
1 st Write Data Cycle	0 0 0 0 R3 R2 R1 R0 G3 G2 G1 G0 B3 B2 B1 B0
2 nd Write Data Cycle	0 0 0 0 R3 R2 R1 R0 G3 G2 G1 G0 B3 B2 B1 B0

LC[7:6] = 10b (RRRRR-GGGGGG-BBBBB, 64K-color)

16 bits of input data are stored to 16 RAM bits directly.

Data Write Sequence (8-bit)	D[7:0]
1 st Write Data Cycle	R4 R3 R2 R1 R0 G5 G4 G3
2 nd Write Data Cycle	G2 G1 G0 B4 B3 B2 B1 B0

Data Write Sequence (16-bit)	D[15:0]
1 st Write Data Cycle	R4 R3 R2 R1 R0 G5 G4 G3 G2 G1 G0 B4 B3 B2 B1 B0

Green Enhance Mode enabled (DC[4]=0):

LC[7:6] = 01b (RRRR-GGGG-BBB, 4K-color)

12 bits of input data are extended and stored to 16 RAM bits. Every 3 bytes of input data will be merged into 2 sets of RGB data.

Data Write Sequence (8-bit)	D[7:0]
1 st Write Data Cycle	R3 R2 R1 R0 G4 G3 G2 G1
2 nd Write Data Cycle	G0 B2 B1 B0 R3 R2 R1 R0
3 rd Write Data Cycle	G4 G3 G2 G1 G0 B2 B1 B0

Data Write Sequence (16-bit)	D[15:0]
1 st Write Data Cycle	0 0 0 0 R3 R2 R1 R0 G4 G3 G2 G1 G0 B2 B1 B0
2 nd Write Data Cycle	0 0 0 0 R3 R2 R1 R0 G4 G3 G2 G1 G0 B2 B1 B0

LC[7:6] = 10b (RRRRR-GGGGGG-BBBBB, 64K-color)

The behaviors of 8-bit input mode and 16-bit input mode do not change with DC[4] setting. Refer to previous section for more information on these two input modes.

For STN display:

LC[7:6] = 01b (1 byte every 2 SEGs)

Data Write Sequence (8-bit)	D[7:0]							
Write-data Cycle	Sn	-	-	-	Sn+1	-	-	-

Data Write Sequence (16-bit)	D[15:0]							
Write-data Cycle	0	0	0	0	Sn	-	-	-

LC[7:6] = 10b (2 bytes every 3 SEGs)

Data Write Sequence (8-bit)	D[7:0]							
1-st Write-data Cycle	Sn	-	-	-	-	Sn+1	-	-
2-nd Write-data Cycle	-	-	-	Sn+2	-	-	-	-

Data Write Sequence (16-bit)	D[15:0]							
Write-data Cycle	Sn	-	-	-	-	Sn+1	-	-

(22) SET COM SCAN FUNCTION

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set COM Scan Function CSF[2:0]	0	0	1	1	0	1	1	CSF2	CSF1	CSF0

COM scan function

CSF[0]: Interlace Scan Function

0b: LRM sequence: AEBCD-AEBCD

1b: LRM sequence: AEBCD-EBCDA

CSF[1]: FRC Function

0b: FRC Disable

1b: FRC Enable

CSF[2]: Shade-1, Shade-30 option

0 : Dither directly on input data(SRAM Change)

1 : PWM on SEG output stage

(23) SYSTEM RESET

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
System Reset	0	0	1	1	1	0	0	0	1	0

This command will activate the system reset. Control register values will be reset to their default values. Data stored in RAM will not be affected.

(24) NOP

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
No Operation	0	0	1	1	1	0	0	0	1	1

This command is used for "no operation".

(25) SET TEST CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set TT	0	0	1	1	1	0	0	1		TT
(Double-byte command)	0	0								Testing parameter

This command is used for UltraChip production testing. Do NOT use.**(26) SET LCD BIAS RATIO**

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Bias Ratio BR [1:0]	0	0	1	1	1	0	1	0	BR1	BR0

Bias ratio definition:

00b = 5

01b = 10

10b = 11

11b = 12

(27) SET COM END

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set CEN (Double-byte command)	0	0	1	1	1	1	0	0	0	1
	0	0	-							

CEN register parameter

This command programs the ending COM electrode. CEN defines the number of used COM electrodes, and it should correspond to the number of pixel-rows in the LCD. When the LCD has less than 160 pixel rows, the LCM designer should set CEN to $N-1$ (where N is the number of pixel rows) and use COM1 through COM- N as COM driver electrodes.

(28) SET PARTIAL DISPLAY START

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set DST (Double-byte command)	0	0	1	1	1	1	0	0	1	0
	0	0	-							

This command programs the starting COM electrode, which has been assigned a full scanning period and will output an active COM scanning pulse.

(29) SET PARTIAL DISPLAY END

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set DEN (Double-byte command)	0	0	1	1	1	1	0	0	1	1
	0	0	-							

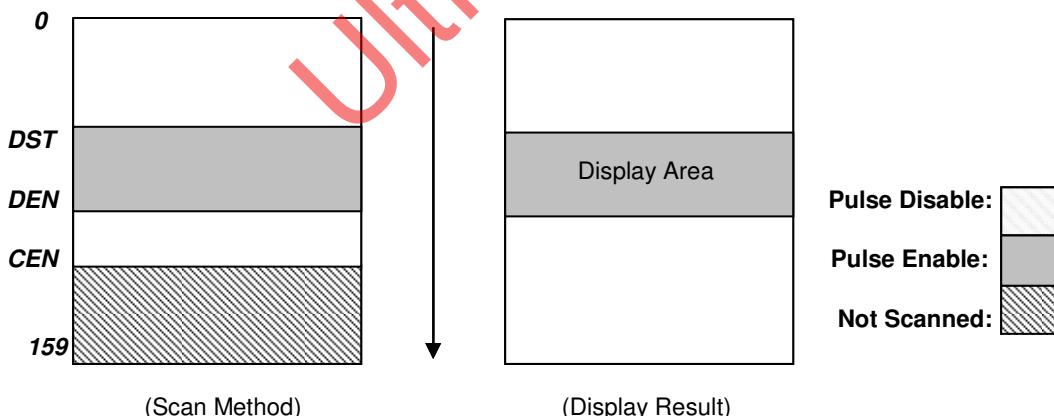
This command programs the ending COM electrode, which has been assigned a full scanning period and will output an active COM scanning pulse.

CEN, DST, and DEN are 0-based index of COM electrodes. They control only the COM electrode activity, and do not affect the mapping of display RAM to each COM electrodes. The image displayed by each pixel row is therefore not affected by the setting of these three registers.

When LC[8]=1b, the Mux-Rate is narrowed down to DEN- DST+1+(FLT+FLB)xLC[0]x2. When MUX rate is reduced, reduce the line rate accordingly to reduce power. Changing MUX rate also require BR and V_{LCD} to be reduced.

For minimum power consumption, set LC[8]=1b, set (DST, DEN, FLT, FLB, CEN) to minimize MUX rate, use slowest line rate which satisfies the flicker requirement, use On/Off mode, set PC[0]=0b, disable N-Line Inversion, and use lowest BR, lowest V_{LCD} which satisfies the contrast requirement. When Mux-Rate is under 40, it is recommended to set BR=5 for optimum power saving.

In either case, DST/DEN defines a small subsection of the display which will remain active while shutting down all the rest of the display to conserve energy.



(30) SET WINDOW PROGRAM STARTING COLUMN ADDRESS

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set WPC0 (Double-byte command)	0	0	1	1	1	1	0	1	0	0
	0	0	-							

This command is to program the starting column address of RAM program window.

(31) SET WINDOW PROGRAM STARTING ROW ADDRESS

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set WPP0 (Double-byte command)	0	0	1	1	1	1	0	1	0	1
	0	0	-							

This command is to program the starting row address of RAM program window.

(32) SET WINDOW PROGRAM ENDING COLUMN ADDRESS

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set WPC1 (Double-byte command)	0	0	1	1	1	1	0	1	1	0
	0	0	-							

This command is to program the ending column address of RAM program window.

(33) SET WINDOW PROGRAM ENDING ROW ADDRESS

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set WPP1 (Double-byte command)	0	0	1	1	1	1	0	1	1	1
	0	0	-							

This command is to program the ending row address of RAM program window.

(34) SET WINDOW PROGRAM MODE

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Window Program Enable AC[3]	0	0	1	1	1	1	1	0	0	AC3

This command controls the Window Program function.

AC[3]=0: Inside Mode

When Window Programming is under "Inside" mode , the CA and RA increment and wrap-around will be performed automatically around the boundaries as defined by registers WPC0, WPC1, WPP0, and WPP1, so that the CA/RA address will stay within the defined window of SRAM address, and therefore allow effective data update within the window.

AC[3]=1: Outside Mode

When Window Programming is under "Outside" mode, the CA and RA increment and wrap-around boundary will cover the entire UC1698u SRAM map (CA: 0~127, RA:0~159). However, when CA/RA points to a memory location within the window defined by registers WPC0, WPC1, WPP0, and WPP1, the SRAM data update operation will be suspended, the existing data will be retained and the input data will be ignored.

The direction of Window Program will depend on the WA (AC[0]), RID (AC[2]), auto-increment order (AC[1]) and MX (LC[1]) register setting.

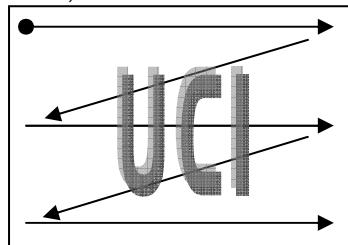
- WA (AC[0]) decides whether the program RAM address advances to next row / column after reaching the specified window column / row boundary.
- RID (AC[2]) controls the RAM address increasing from WPP0 toward WPP1 (RID=0) or the reverse direction (RID=1).
- Auto-increment Order (AC[1]) directs the RAM address increasing vertically (AC[1]=1) or horizontally (AC[1]=0).
- MX (LC[1]) results the RAM column address increasing from 127-WPC0 to 127-WPC1 (MX=1) or from WPC0 to WPC1 (MX=0).

By different combination of RID, AC[1], MX, and by setting CA, RA at proper corners of the "window", effects such as mirrors and rotations can be easily achieved.

Setting or resetting AC[3] does not affect the values of CA and RA. So, always remember to reposition CA and RA properly after changing the setting of AC[3].

Auto-increment order = 0 MX=0 RID = 0

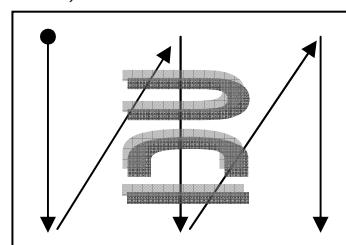
(WPP0,WPC0)



(WPP1,WPC1)

Auto-increment order = 1 MX=0 RID = 0

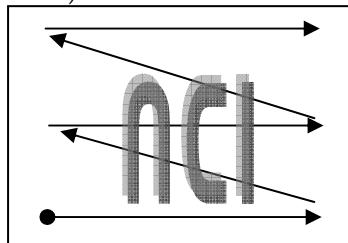
(WPP0,WPC0)



(WPP1,WPC1)

Auto-increment order = 0 MX=0 RID = 1

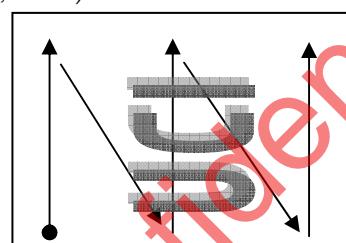
(WPP0,WPC0)



(WPP1,WPC1)

Auto-increment order = 1 MX=0 RID = 1

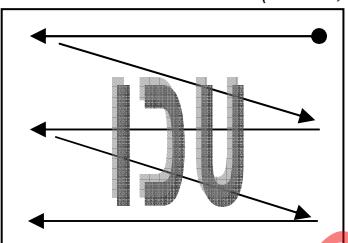
(WPP0,WPC0)



(WPP1,WPC1)

Auto-increment order = 0 MX=1 RID = 0

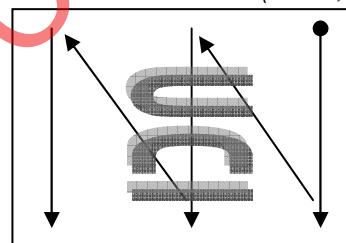
(WPP0,127-WPC0)



(WPP1,127-WPC1)

Auto-increment order = 1 MX=1 RID = 0

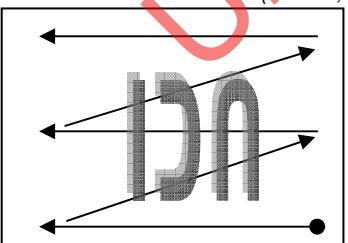
(WPP0,127-WPC0)



(WPP1,127-WPC1)

Auto-increment order = 0 MX=1 RID = 1

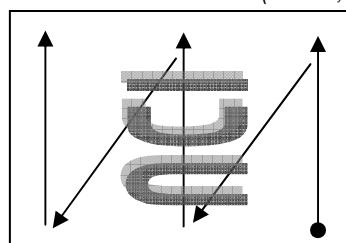
(WPP0,127-WPC0)



(WPP1,127-WPC1)

Auto-increment order = 1 MX=1 RID = 1

(WPP0,127-WPC0)



(WPP1,127-WPC1)

LCD VOLTAGE SETTING

MULTIPLEX RATES

Multiplex Rate is completely software programmable in UC1698u via registers CEN, DST, DEN, FLT, FLB, and partial display control flags LC[8] and LC[0].

Combined with low power partial display mode and a low bias ratio of 6, UC1698u can support wide variety of display control options. For example, when a system goes into standby mode, a large portion of LCD screen can be turned off to conserve power.

BIAS RATIO SELECTION

Bias Ratio (*BR*) is defined as the ratio between V_{LCD} and V_{BIAS} , i.e.

$$BR = V_{LCD} / V_{BIAS},$$

where $V_{BIAS} = V_{B1+} - V_{B1-} = V_{B0+} - V_{B0-}$.

The theoretical optimum *Bias Ratio* can be estimated by $\sqrt{Mux} + 1$. *BR* of value 15~20% lower/higher than the optimum value calculated above will not cause significant visible change in image quality.

Due to the nature of STN operation, an LCD designed for good gray-shade performance at high Mux Rate (e.g. MR=160), can generally perform very well as a black and white display, at lower Mux Rate. However, it is also true that such technique generally can not maintain LCD's quality of gray shade performance, since the contrast of the LCD will increase as Mux Rate decreases, and the shades near the two ends of the spectrum will start to lose visibility.

UC1698u supports four *BR* as listed below. *BR* can be selected by software program.

BR	0	1	2	3
Bias Ratio	5	10	11	12

Table 1: Bias Ratios

TEMPERATURE COMPENSATION

Four different temperature compensation coefficients can be selected via software. The four coefficients are given below:

TC	0	1	2	3
% per $^{\circ}\text{C}$	-0.00	-0.05	-0.15	-0.25

Table 2: Temperature Compensation

V_{LCD} AND CONTRAST FINE TUNING

Color STN LCD is sensitive to even a 0.5% mismatch between IC driving voltage and the V_{OP} of LCD. It is very difficult for LCD makers to guarantee such high precision matching of parts from different vendors. It is therefore necessary to adjust V_{LCD} to precisely match the actual V_{OP} of each LCD.

For the best results, software or MTP based V_{LCD} adjustment is the recommended method for V_{LCD} fine tuning. System designers should always consider the contrast fine tuning requirement before finalizing on the LCM design.

LOAD DRIVING STRENGTH FOR COG

The power supply circuit of UC1698u is designed to handle LCD panels with loading up to $\sim 18\text{nF}$ using $7\text{-}\Omega/\text{Sq}$ ITO glass with $V_{DD2/3} \geq 2.8\text{V}$. For larger LCD panels, use lower resistance ITO glass.

Due to crosstalk consideration, $\sim 18\text{nF}$ is also the recommended maximum LCD panel loading for COG applications. Using $4.5\text{-}\Omega/\text{Sq}$ low resistance ITO glass will help improve image quality and operation tolerance.

V_{LCD} GENERATION

V_{LCD} may be supplied either by internal charge pump or by external power supply. The source of V_{LCD} is controlled by PC[1].

When V_{LCD} is generated internally, the voltage level of V_{LCD} is determined by three control registers: BR (Bias Ratio), PM (Potentiometer), and TC (Temperature Compensation), with the following relationship:

$$V_{LCD} = (C_{V0} + C_{PM} \times PM) \times (1 + (T - 25) \times C_T \%)$$

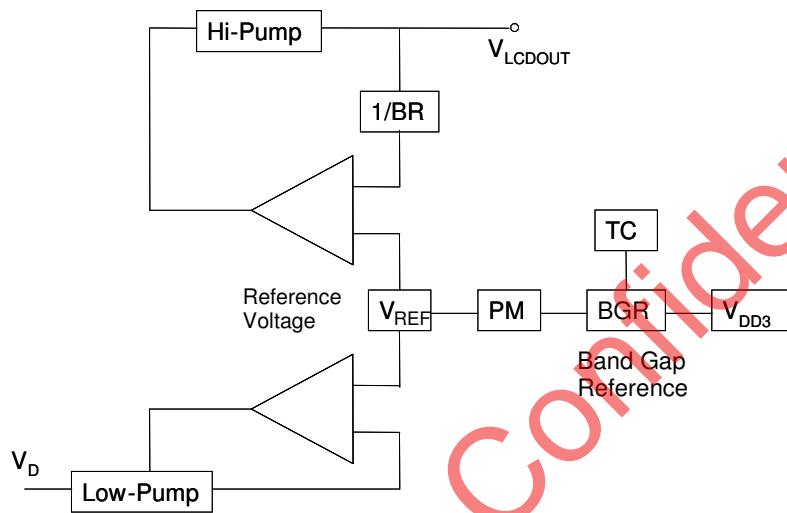
where

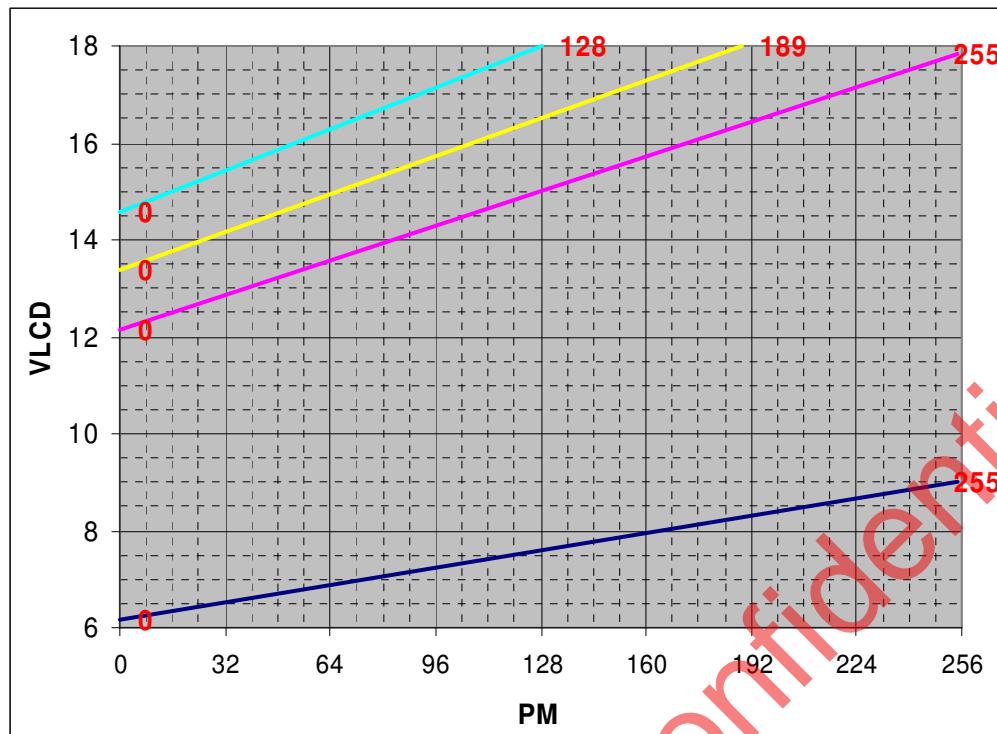
C_{V0} and C_{PM} are two constants, whose value depends on the setting of BR register, as illustrated in the table on the next page,

PM is the numerical value of PM register,

T is the ambient temperature in $^{\circ}\text{C}$, and

C_T is the temperature compensation coefficient as selected by TC register.



V_{LCD} QUICK REFERENCE

BR	C _{v0} (V)	C _{PM} (mV)	PM_reg	V _{LCD} (V)
5	6.154	11.22	0	6.154
			255	9.015
10	12.157	22.26	0	12.157
			255	17.833
11	13.369	24.45	0	13.369
			189	17.991
12	14.580	26.61	0	14.580
			128	17.986

V_{LCD}-PM-BR relationship at 25°C

NOTE:

1. For good product reliability, please keep V_{LCD} under **18V** over all temperature, and **17.5V** at -40°C.
2. The integer values of BR above are for reference only and may have slight shift.

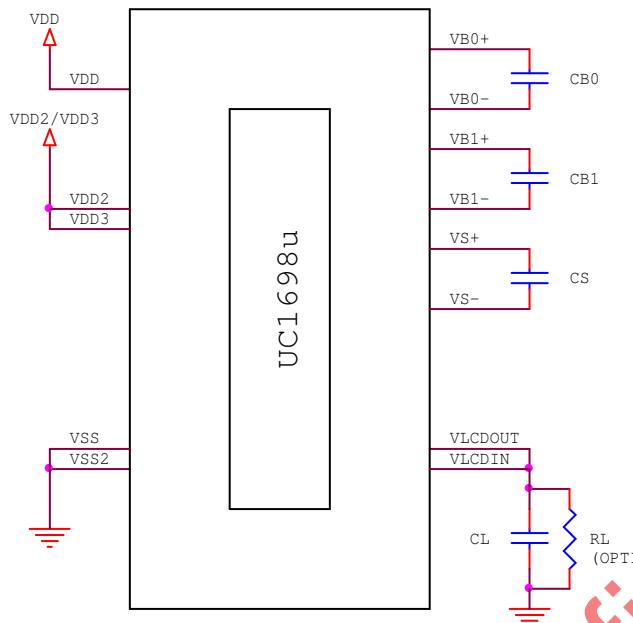
Hi-V GENERATOR REFERENCE CIRCUIT

FIGURE 1: Sample circuit using internal Hi-V generator circuit

NOTE:

Sample component values: (The illustrated circuit and component values are for reference only. Please optimize for specific requirements of each application.)

$C_{B0\sim 1}$: 2.2 μ F/5V or 300x LCD load capacitance, whichever is higher.

C_L : 330nF(25V) is appropriate for most applications.

C_S : 150 ~ 220nF / 25V.

R_L : 3.3 ~ 10 M Ω to act as a draining circuit when V_{DD} is shut down abruptly.

LCD DISPLAY CONTROLS

CLOCK & TIMING GENERATOR

UC1698u contains a built-in system clock. All required components for the clock oscillator are built-in. No external parts are required.

Four different line rates are provided for system design flexibility. The line rate is controlled by register LC[4:3]. When Mux-Rate is above 109, frame rate is calculated as:

$$\text{Frame Rate} = \text{Line-Rate} / \text{Mux-Rate}.$$

When Mux-Rate is lowered to 108, 80, 56 and 40, line rate will be scaled down automatically by 1.5, 2, 3 and 4 times to reduce power consumption.

Flicker-free frame rate is dependent on LC material and gray-shade modulation scheme. Line rate 37.0 Kbps or higher is recommended for 32-shade mode. Choose lower frame rate for lower power, and choose higher frame rate to improve LCD contrast and minimize flicker.

When switching from 32-shade modulation to On/Off Mode, line rate will be scaled down automatically to reduce power.

Under most situations, flicker behavior is similar between these two modulation schemes. However, it is recommended to test each mode to make sure the result is as expected.

DRIVER MODES

COM and SEG drivers can be in either Idle mode or Active mode, controlled by Display Enable flag (DC[2]). When SEG drivers are in Idle mode, they will be connected together to ensure zero DC condition on the LCD.

DRIVER ARRANGEMENTS

The naming convention is COM(x), where x=1~160, referring to the COM driver for the x-th row of pixels on the LCD panel.

The mapping of COM(x) to LCD pixel rows is fixed and it is not affected by SL, CST, CEN, DST, DEN, MX or MY settings.

DISPLAY CONTROLS

There are three groups of display control flags in the control register DC: Driver Enable (DE), All-Pixel-ON (APO) and Inverse (PXV). DE has the overriding effect over PXV and APO.

DRIVER ENABLE (DE)

Driver Enable is controlled by the value of DC[2] via the Set Display Enable command. When DC[2] is set to OFF (logic "0"), both COM and SEG drivers will become idle and UC1698u will put itself into Sleep mode to conserve power.

When DC[2] is set to ON, the DE flag will become "1", and UC1698u will first exit from Sleep mode, restore the power (V_{LCD} , V_D etc.) and then turn on COM and SEG drivers.

ALL PIXELS ON (APO)

When set, this flag will force all SEG drivers to output ON signals, disregarding the data stored in the display buffer.

This flag has no effect when Display Enable is OFF and it has no effect on data stored in RAM.

INVERSE (PXV)

When this flag is set to ON, SEG drivers will output the inverse of the value it received from the display buffer RAM (bit-wise inversion). This flag has no impact on data stored in RAM.

PARTIAL SCROLL

Control register FLT and FLB specify two regions of rows which are not affected by the SL register. Since SL register can be used to implement scroll function. FLT and FLB registers can be used to implement fixed regions when the other part of the display is scrolled by SL.

PARTIAL DISPLAY

UC1698u provides flexible control of Mux Rate and active display area. Please refer to commands Set COM End, Set Partial Display Start, and Set Partial Display End for more detail.

GRAY-SHADE MODULATION MODE

UC1698u has two gray-shade modulation modes: 32-shade and On/Off Mode.

The On/Off mode will consume roughly 40~45% less power than the 32-shade mode, and can be used for situations where power consumption is more critical than color fidelity.

Changing gray-shade modulation mode does not affect the content of SRAM display buffer, and the image data will remain the same after switching back and forth between On/Off mode and 32-shade mode.

INPUT COLOR FORMATS

UC1698u supports the following two different input color formats.

4KC (12-bit/RGB): In this color mode, R/G/B will be extended and the input data will be converted into 5R-6G-5B format before they are stored to display RAM.

64KC (16-bit/RGB): This is the native color mode. Data will be stored directly to on-chip SRAM in 5R-6G-5B (16-bit) format (except shade1 and shade30, which are achieved by special dithering. See command Set Display Enable for more details). This is the default input format mode.

Changing color mode does not affect the content already stored in the display buffer RAM. Users can mix several color modes together and switch among them in real time.

For example, the menu portion can be painted in 4K-color mode for fast update speed, and then switch to 64K-color mode, together with window programming function to effectively produce smooth graphics images.

ITO LAYOUT AND LC SELECTION

Since COM scanning pulses of UC1698u can be as short as 13μS, it is critical to control the RC delay of COM and SEG signal to minimize crosstalk and maintain good mass production consistency.

COM TRACES

Excessive COM scanning pulse RC decay can cause fluctuation of contrast and increase COM direction crosstalk.

Please limit the worst case of COM signals RC delay ($R_{C_{MAX}}$) as calculated below

$$(R_{ROW} / 2.7 + R_{COM}) \times C_{ROW} < 0.8\mu S$$

where

C_{ROW} : LCD loading capacitance of one row of pixels. It can be calculated by $C_{LCD}/\text{Mux-Rate}$, where C_{LCD} is the LCD panel capacitance.

R_{ROW} : ITO resistance over one row of pixels within the active area

R_{COM} : COM routing resistance from IC to the active area + COM driver output impedance.

In addition, please limit the min-max spread of RC decay to be:

$$| R_{C_{MAX}} - R_{C_{MIN}} | < 0.15\mu S$$

so that the COM distortions on the top of the screen to the bottom of the screen are uniform.

(Use worst case values for all calculations)

SEG TRACES

Excessive SEG signal RC decay can cause image dependent changes of medium gray shades and sharply increase of SEG direction crosstalk.

For good image quality, please minimize SEG ITO trace resistance and limit the worst case of SEG signal RC delay as calculated below.

$$(R_{COL} / 2.7 + R_{SEG}) \times C_{COL} < 0.3\mu S$$

where

C_{COL} : LCD loading capacitance of one pixel column. It can be calculated by $C_{LCD} / \#_{\text{column}}$, where C_{LCD} is the LCD panel capacitance.

R_{COL} : ITO resistance over one column of pixels within the active area

R_{SEG} : SEG routing resistance from IC to the active area + SEG driver output impedance.

(Use worst case values for all calculations)

SELECTING LIQUID CRYSTAL

The selection of LC material is crucial to achieve the optimum image quality of finished LCM.

When $(V_{90}-V_{10})/V_{10}$ is too high, image contrast and color saturation will deteriorate, and images will look murky and dull.

When $(V_{90}-V_{10})/V_{10}$ is too small, image contrast will become too strong, visibility of shades will suffer, and crosstalk may increase sharply for medium shades.

For the best result, it is recommended the LC material has the following characteristics:

$$(V_{90}-V_{10})/V_{10} = (V_{ON}-V_{OFF})/V_{OFF} \times 0.72 \sim 0.80$$

where V_{90} and V_{10} are the LC characteristics, and V_{ON} and V_{OFF} are the ON and OFF V_{RMS} voltage produced by LCD driver IC at the specific Mux-rate.

Two examples are provided below:

Duty	Bias	$V_{ON}/V_{OFF}-1$	x0.80	x0.72
1/160	1/12	7.93%	6.3%	5.7%
1/160	1/11	7.77%	6.2%	5.6%

VIDEO CSTN & COG

UC1698u can support very fast CSTN for video rate applications. For LCM with $t_s+t_f = 180\text{mS} \sim 200\text{mS}$ or smaller, it is recommended to set the line rate higher such that the frame rate is 260Hz or higher. For such applications, special attentions are necessary for COG design to minimize crosstalk and to ensure plenty of power is available to drive the LCM at such high speed.

- At this fast scan rate, the SEG/COM trace RC decay minimization will be very critical in minimizing crosstalk.
- MPU will perform frequent high speed update to the on-chip video RAM for video applications. Make sure the ITO does not cause on-chip $V_{DD}-V_{SS}$ to fall below 1.7V, and V_{SS} bounce is under $7\% \times V_{DD}$.

For VSTN (video CSTN) applications, it is recommended to use low resistance ITO glass to help reducing SEG signal RC decay, minimizing V_{DD} , V_{SS} noise, and ensuring sufficient V_{DD2} , V_{SS2} supply for on-chip DC-DC converter.

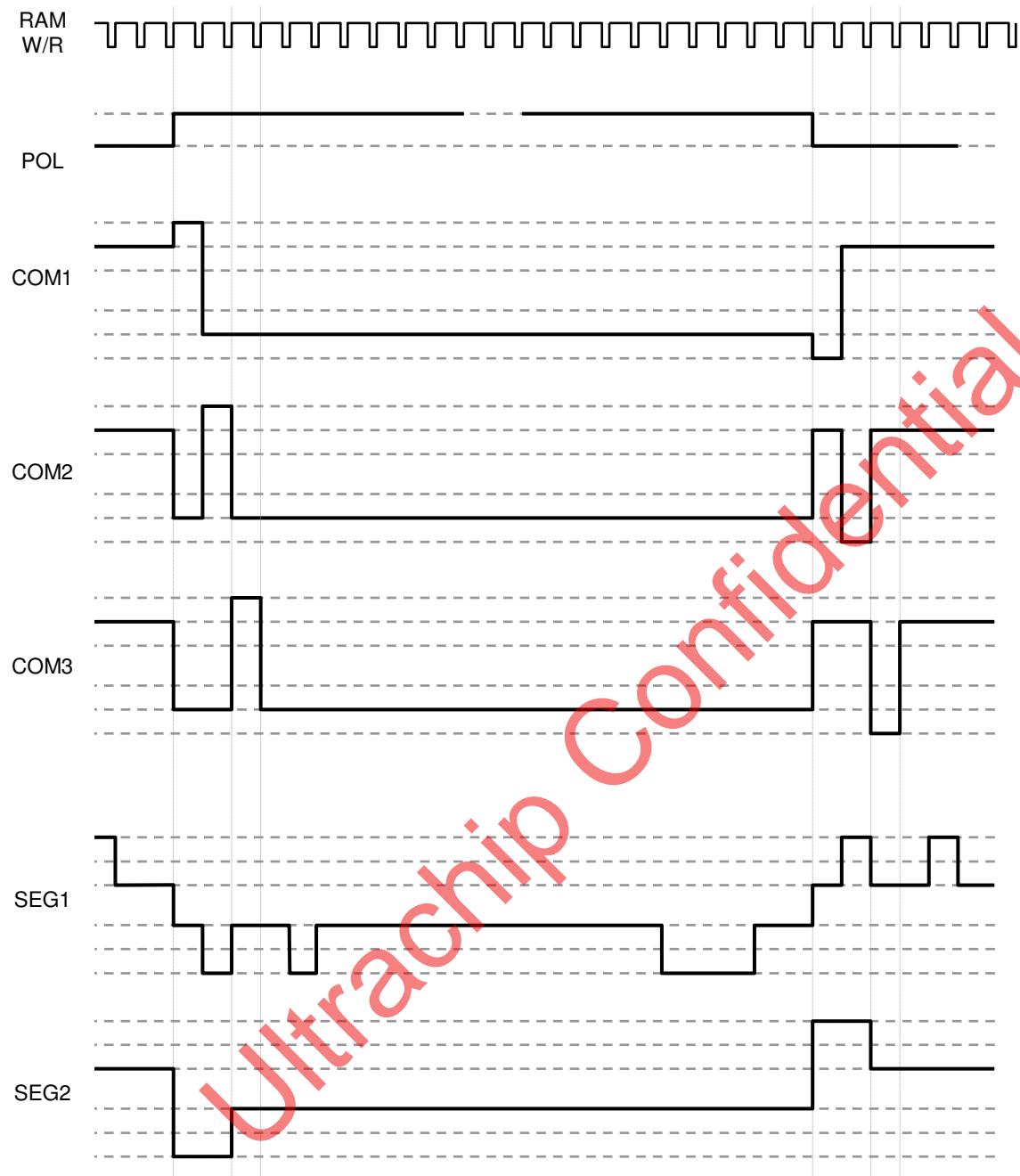


FIGURE 2: COM and SEG Driving Waveform

HOST INTERFACE

As summarized in the table below, UC1698u supports two (2) parallel bus protocols, in either 8-bit or 16-bit bus width, and three (3) serial bus protocols.

Designers can either use parallel bus to achieve high data transfer rate, or use serial bus to create compact LCD modules.

		Bus Type								
		8080		6800		S8 (4wr)	S8uc(3/4wr)	S9 (3WR)		
Width		16-bit	8-bit	16-bit	8-bit	Serial				
Control & Data Pins	Access	Read/Write					Write Only			
	BM[1:0]	10	00	11	01	00	00	01		
	{DB[15], DB[13]}	Data	0x	Data	0x	10	11	10		
	CS[1:0]	Chip Select								
	CD	Control / Data					0			
	WR0	WR		R/W		0				
	WR1	RD		EN		0				
DB[1,3,5,7,9,11]		Data	-	Data	-	-				
DB[0,2,4,6,8,10,12,14]		Data	Data	Data	Data	DB[8]=SDA, DB[0]=SCK				

* Connect unused control pins and data bus pins to V_{DD} or V_{SS}.

	CS Disable Interface	CS Init bus state	CD 1↔0 Init bus state	CD 1⇒0 init color mapping	RESET Init bus state	RESET init color mapping
16-bit	✓	-	-	✓	✓	✓
8-bit	✓	-	-	✓	✓	✓
S8	✓	✓	-	✓	✓	✓
S8uc	✓	-	✓	✓	✓	✓

- CS disable bus interface – CS can be used to disable Bus Interface Write / Read Access.
- CD refers to CD transitions within valid CS window. CD = 0 means write command or read status.
- CS Sync / RESET can be used to initialize bus state machine (like 8-bit / S8 / S9).
- RESET can be pin reset / soft reset / power on reset.
- CD can be used to initialize the multi-byte input RGB format to/from on-chip SRAM mapping.

Table 3: Host interfaces Summary

PARALLEL INTERFACE

The timing relationship between UC1698u internal control signal RD, WR and their associated bus actions are shown in the figure below.

The Display RAM read interface is implemented as a two-stage pipe-line. This architecture requires that, every time memory address is modified, either in 8-bit mode or 16-bit mode, by either *Set CA*, or *Set RA* command, a dummy read cycle needs to be performed before the actual data can propagate through the pipe-line and be read from data port D.

There is no pipeline in write interface of Display RAM. Data is transferred directly from bus buffer to internal RAM on the rising edges of write pulses.

16-BIT & 8-BIT BUS OPERATION

UC1698u supports both 8-bit and 16-bit bus width. The bus width is determined by pin BM[1].

8-bit bus operation exactly doubles the clock cycles of 16-bit bus operation, MSB followed by LSB, including the dummy

read, which also requires two clock cycles. The bus cycle of 8-bit mode is reset each time CD pin changes state (when CS is active).

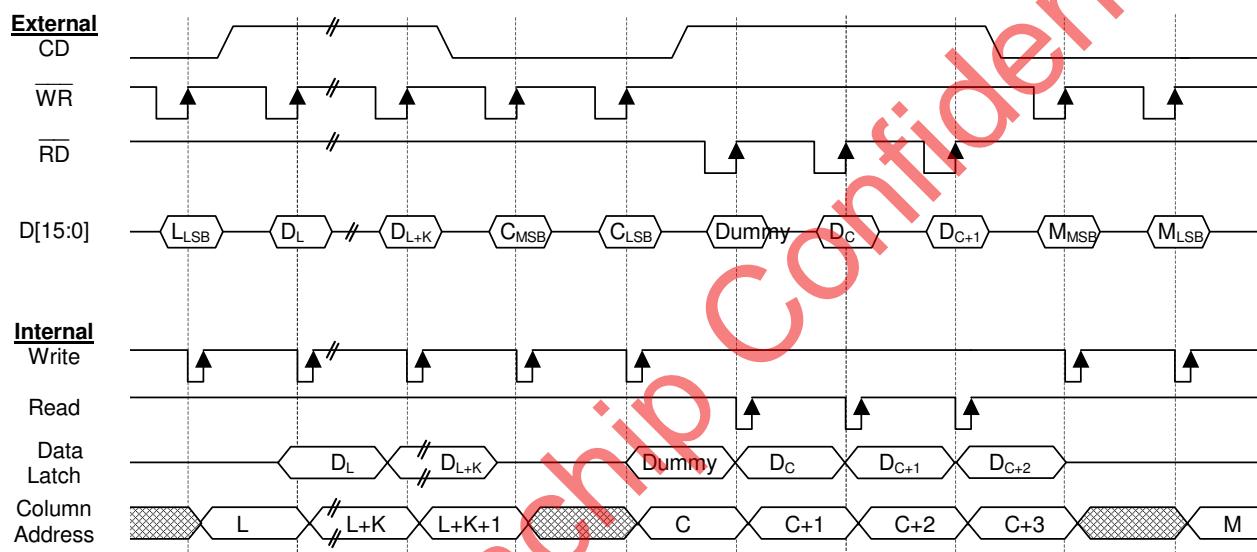


FIGURE 3: 16-bit Parallel Interface & Related Internal Signals

SERIAL INTERFACE

UC1698u supports three serial modes, one 4-wire SPI mode (S8), one compact 3/4-wire mode (S8uc), and one 3-wire mode (S9). Bus interface mode is determined by the wiring of the BM[1:0], D[15] and D[13]. See table in last page for more detail.

S8 (4-WIRE) INTERFACE

Only write operations are supported in 4-wire serial mode. Pins CS[1:0] are used for chip select and bus cycle reset. Pin CD is used to determine the content of the data been transferred. During each write cycle, 8 bits of data, MSB first, are latched on eight rising SCK edges into an 8-bit data holder.

If CD=0, the data byte will be decoded as command. If CD=1, this 8-bit will be treated as data and transferred to proper address in the Display Data RAM on the rising edge of the last SCK pulse. Pin CD is examined when SCK is pulled low for the LSB (D0) of each token.

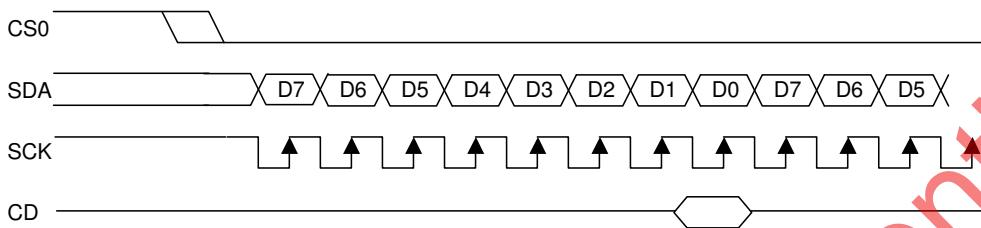


FIGURE 4.a: 4-wire Serial Interface (S8)

S8uc (3/4-WIRE) INTERFACE

Only write operations are supported in this 3/4-wire serial mode. The data format is identical to S8. The CD pin transitions will reset the bus cycle in this mode. So, if CS pins

are hardwired to enable chip-select, the bus can work properly with only three signal pins.

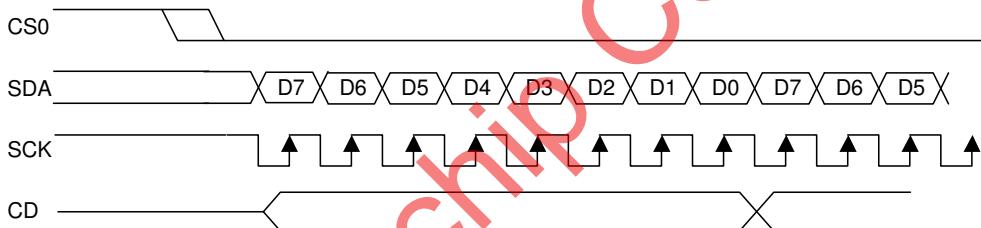


FIGURE 4.b: 3/4-wire Serial Interface (S8uc)

S9 (3-WIRE) INTERFACE

Only Write operation is supported in this 3-wire serial mode. Pins CS[1:0] are used for chip select and bus cycle reset. On each Write cycle, the first bit is CD, which determines the interpretation of the following 8 bits of data, MSB first. These 8 command/data bits are latched on rising SCK edges into an 8-bit data holder. If CD=0, the following byte will be decoded as command.

If CD=1, the following byte will be treated as data and transferred to proper address in the Display Data RAM at the rising edge of the last SCK pulse.

By sending CD information explicitly in the bit stream, control pin CD is not used, and should be connected to either V_{DD} or V_{SS}. The toggle of CS0 or CS1 for each byte of data/command is recommended but optional.

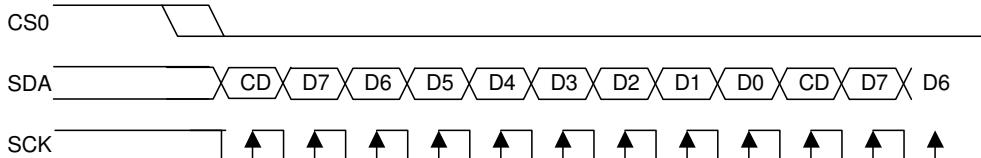


FIGURE 4.c: 3-wire Serial Interface (S9)

HOST INTERFACE REFERENCE CIRCUIT

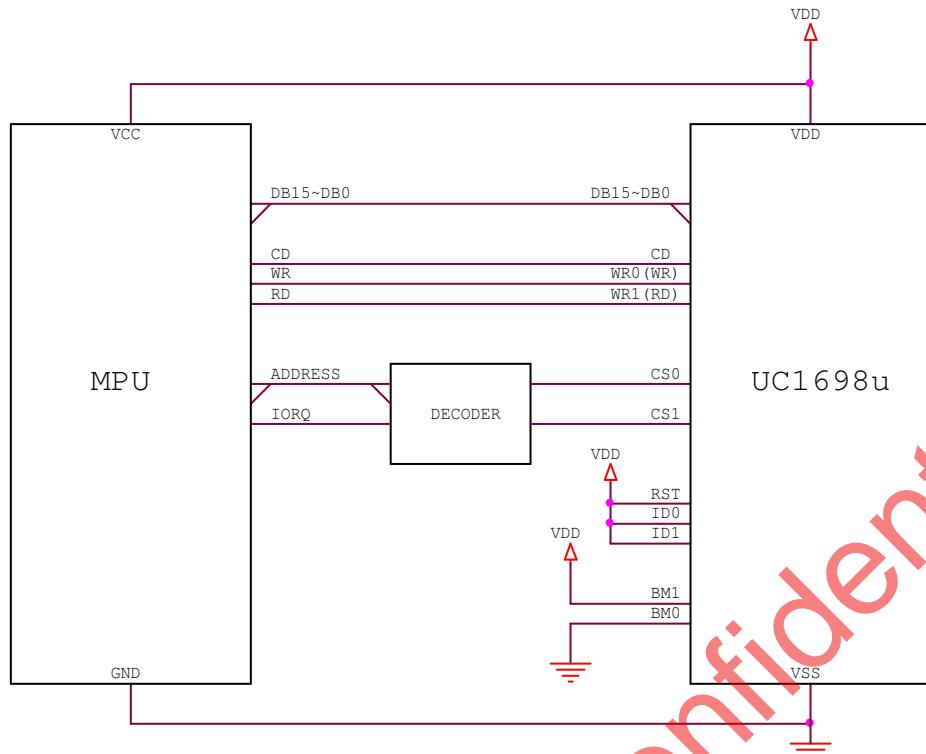


FIGURE 5: 8080/16-bit parallel mode example

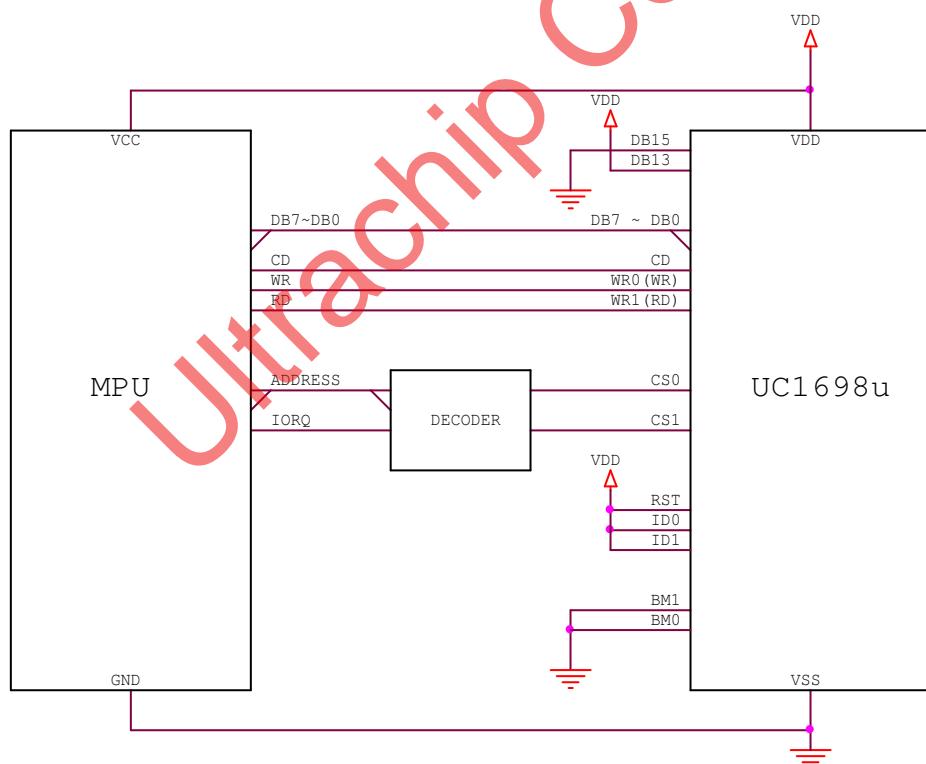


FIGURE 6: 8080/8-bit parallel mode example

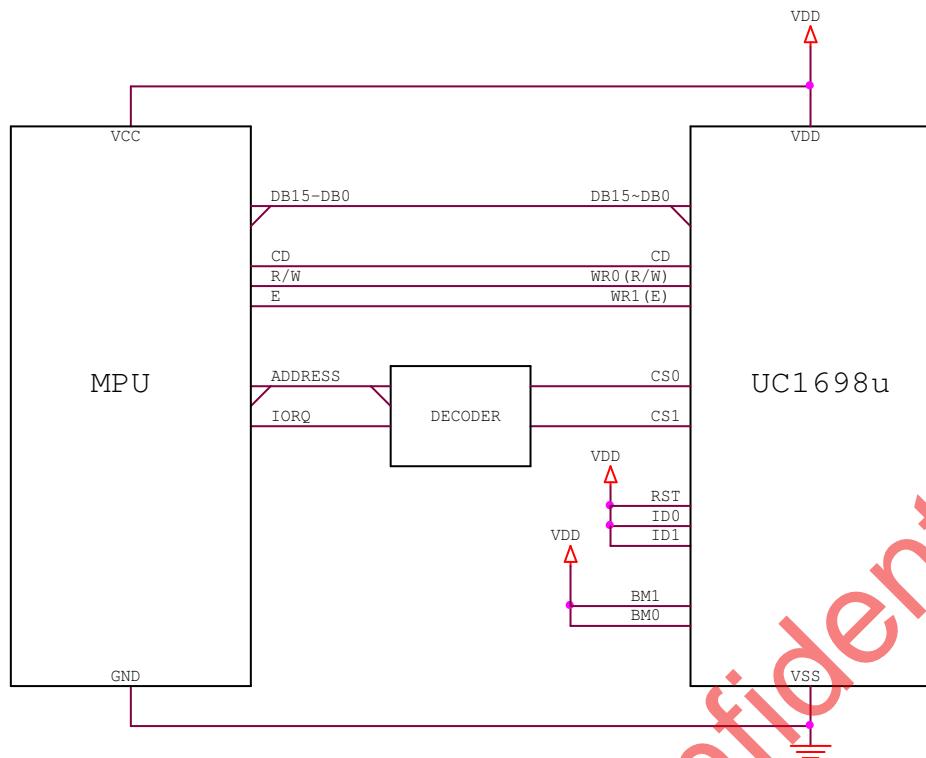


FIGURE 7: 6800/16-bit parallel mode example

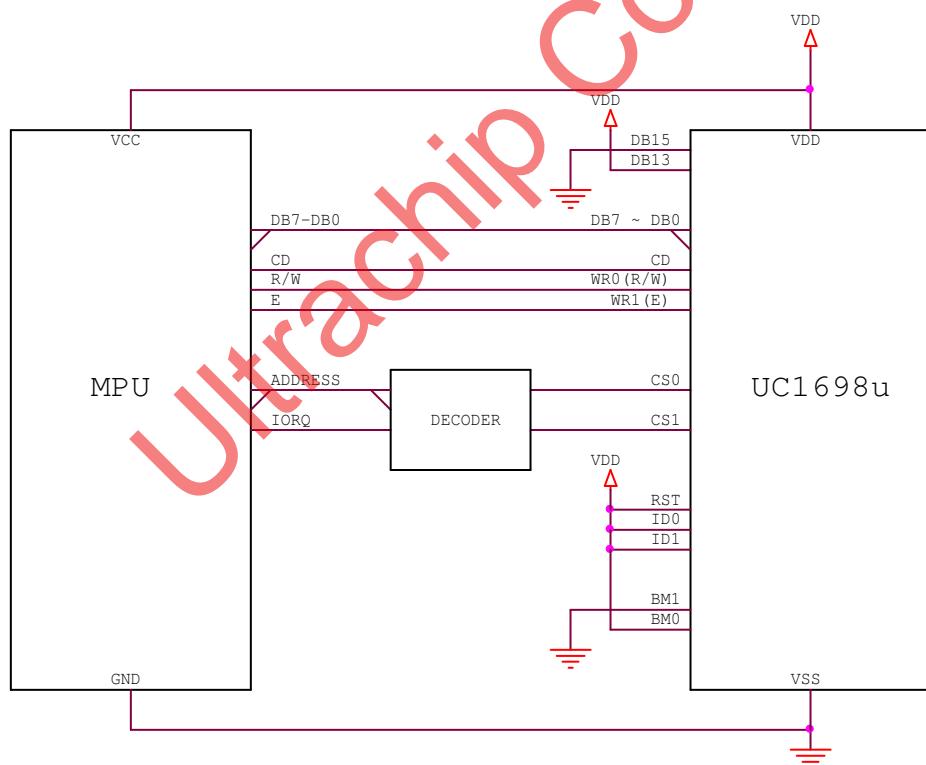


FIGURE 8: 6800/8-bit parallel mode example

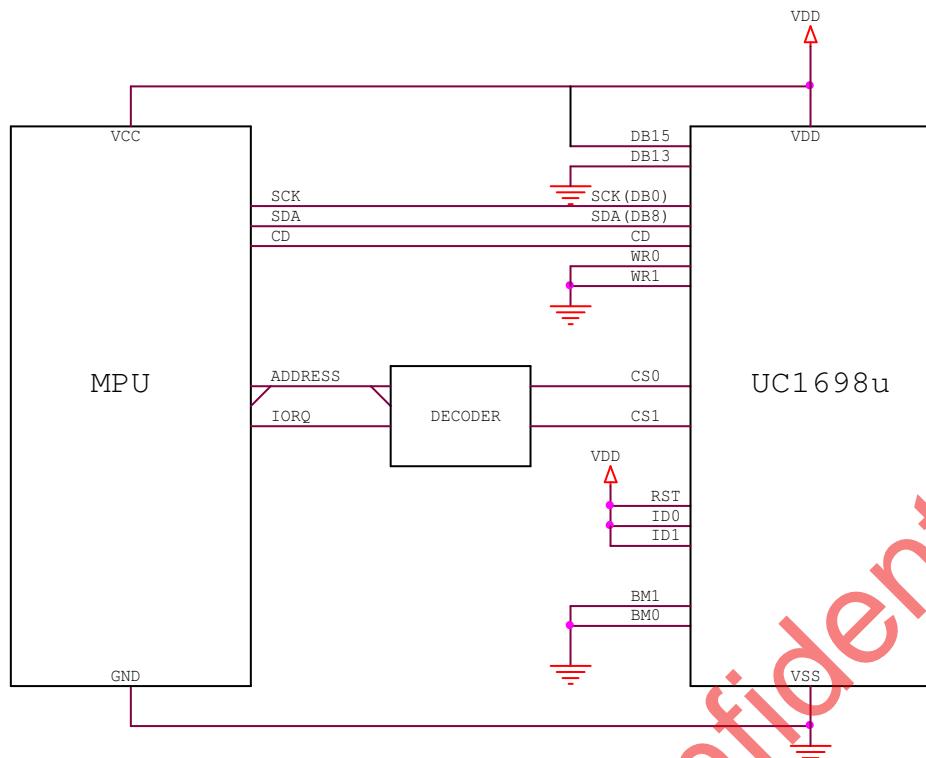


FIGURE 9: 4-Wires SPI (S8) serial mode example

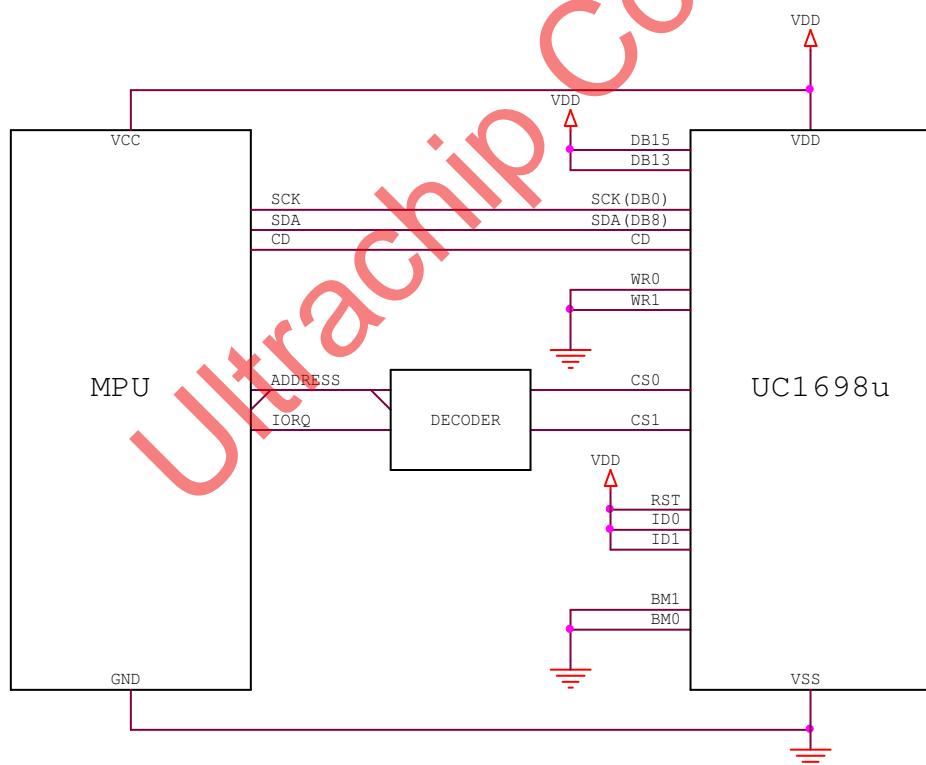


FIGURE 10: 3/4-Wires SPI (S8uc) serial mode example

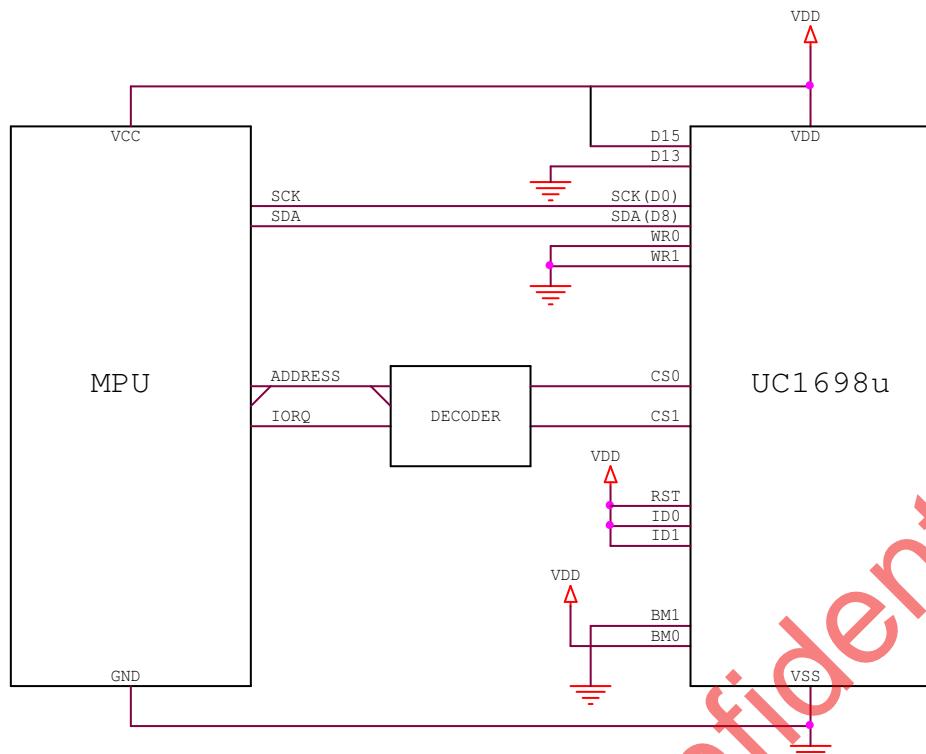


FIGURE 11: 3-Wire (S9) mode example

Note

- Pins ID0 and ID1 are for production control. Their connection will affect the content of D[3:2] of the third byte of the Get Status command. Connect to V_{DD} for "H" or V_{SS} for "L".
- The RST pin is optional. Connect it to V_{DD} when not used.

DISPLAY DATA RAM

DATA ORGANIZATION

The input display data are stored to a dual port static RAM (RAM, for Display Data RAM) organized as 160x128x16 for color CSTN and 160x384x(16/3) for STN.

After setting CA and RA, the subsequent data write cycles will store the data for the specified pixel to the proper memory location.

Please refer to the map in the following page between the relation of COM, SEG, SRAM, and various memory control registers.

DISPLAY DATA RAM ACCESS

The Display RAM is a special purpose dual port RAM which allows asynchronous access to both its column and row data. Thus, RAM can be independently accessed both for Host Interface and for display operations.

DISPLAY DATA RAM ADDRESSING

A Host Interface (HI) memory access operation starts with specifying Row Address (RA) and Column Address (CA) by issuing *Set Row Address* and *Set Column Address* commands.

If wrap-around (WA, AC[0]) is OFF (0), CA will stop incrementing after reaching the end of row (159), and system programmers need to set the values of RA and CA explicitly.

If WA is ON (1), when CA reaches the end of a row, CA will be reset to 0 and RA will increment or decrement, depending on the setting of row Increment Direction (RID, AC[2]). When RA reaches the boundary of RAM (i.e. RA = 0 or 159), RA will be wrapped around to the other end of RAM and continue.

MX IMPLEMENTATION

Column Mirroring (MX) is implemented by selecting either (CA) or (127-CA) as the RAM column address. Changing MX affects the data written to the RAM.

Since MX has no effect on the data already stored in RAM, changing MX does not have immediate effect on the displayed pattern. To refresh the display, refresh the data stored in RAM after setting MX.

Row Mapping

COM electrode scanning orders are not affected by Start Line (SL), Fixed Line (FLT & FTB) or Mirror Y (MY, LC[3]). Visually, register SL having a non-zero value is equivalent to scrolling the LCD display up or down (depends on MY) by *SL* rows.

RAM ADDRESS GENERATION

The mapping of the data stored in the display SRAM and the scanning COM electrodes can be obtained by combining the fixed COM scanning sequence and the following RAM address generation formula.

When FLT & FLB=0, during the display operation, the RAM line address generation can be mathematically represented as following:

For the 1st line period of each field

$$\text{Line} = \text{SL}$$

Otherwise

$$\text{Line} = \text{Mod}(\text{Line}+1, 160)$$

Where Mod is the modular operator, and *Line* is the bit slice line address of RAM to be outputted to SEG drivers. Line 0 corresponds to the first bit-slice of data in RAM.

The above *Line* generation formula produces the “loop around” effect as it effectively resets *Line* to 0 when *Line*+1 reaches 160. Effects such as scrolling can be emulated by changing SL dynamically.

MY IMPLEMENTATION

Row Mirroring (MY) is implemented by reversing the mapping order between COM electrodes and RAM, i.e. the mathematical address generation formula becomes:

For the 1st line period of each field

$$\begin{aligned} \text{Line} = \text{Mod}(\text{SL} + \text{MUX}-1, 160) \\ \text{where MUX} = \text{CEN} + 1 \end{aligned}$$

Otherwise

$$\text{Line} = \text{Mod}(\text{Line}-1, 160)$$

Visually, the effect of MY is equivalent to flipping the display upside down. The data stored in display RAM are not affected by MY.

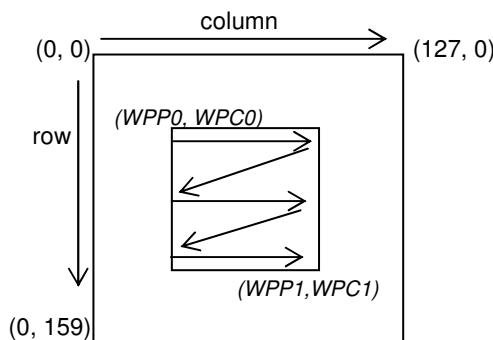
WINDOW PROGRAM

Window program is designed for data write in a specified window range of SRAM address. The procedure should start with window boundary registers setting ($WPP0$, $WPP1$, $WPC0$ and $WPC1$) and AC[3] setting for inside/outside window mode. When AC[3] is set to '0' (default value), data can be written to SRAM within the window address range which is specified by ($WPP0$, $WPC0$) and ($WPP1$, $WPC1$). When AC[3] is set to '1', data will be written to whole SRAM excluding the specified window area.

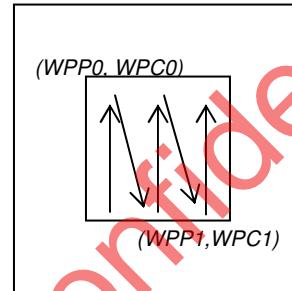
The data write direction will be determined by AC[2:0] and MX settings. When AC[0]=1, the data write can be consecutive within the range of the specified window. AC[1] will control the data write in either column or row direction. AC[2] will result the data write starting either from row $WPP0$ or WPP1. MX is for the initial column address either from $WPC0$ to $WPC1$ or from (MC-WPC0) to MC-WPC1).

Example1 (AC[2:0] = 001) :

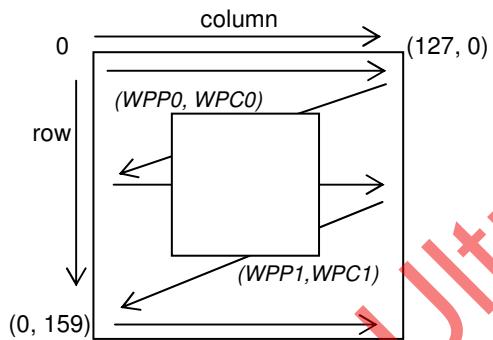
AC[3]=0 MX=0

**Example 2 (AC[2:0] = 111) :**

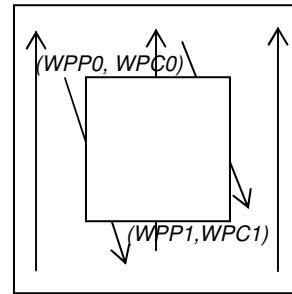
AC[3] = 0 MX = 0

**Example1-1 :**

AC[3]=1 MX=0

**Example 2-1 :**

AC[3] = 1 MX = 0



For Color Display:

Row Address	RAM					
00H	Blue	Green	Red			
01H						
02H						
03H						
04H						
05H						
06H						
07H						
08H						
09H						
0AH						
0BH						
0CH						
0DH						
0EH						
0FH						
10H						
11H						
12H						
13H						
14H						
15H						
16H						
17H						
18H						
19H						
1AH						
1BH						
1CH						
88H						
89H						
8AH						
8BH						
8CH						
8DH						
8EH						
8FH						
90H						
91H						
92H						
93H						
94H						
95H						
96H						
97H						
98H						
99H						
9AH						
9BH						
9CH						
9DH						
9EH						
9FH						

MY=0 SL=0	MY=1 SL=0
COM1	COM17
COM2	COM18
COM3	COM19
COM4	COM20
COM5	COM21
COM6	COM22
COM7	COM23
COM8	COM24
COM9	COM25
COM10	COM26
COM11	COM27
COM12	COM28
COM13	COM29
COM14	COM30
COM15	COM31
COM16	COM32
COM17	COM33
COM18	COM34
COM19	COM35
COM20	COM36
COM21	COM37
COM22	COM38
COM23	COM39
COM24	COM40
COM25	COM41
COM26	COM42
COM27	COM43
COM28	COM44
COM29	COM45
COM137	COM153
COM138	COM154
COM139	COM155
COM140	COM156
COM141	COM157
COM142	COM158
COM143	COM159
COM144	COM160
COM145	COM1
COM146	COM2
COM147	COM3
COM148	COM4
COM149	COM5
COM150	COM6
COM151	COM7
COM152	COM8
COM153	COM9
COM154	COM10
COM155	COM11
COM156	COM12
COM157	COM13
COM158	COM14
COM159	COM15
COM160	COM16

MX	0	1	SEG382	SEG381	SEG380	SEG383	SEG384
			SEG383	SEG382	SEG381	SEG380	SEG384
			SEG382	SEG381	SEG380	SEG383	SEG384
			SEG383	SEG382	SEG381	SEG380	SEG384
			SEG384	SEG383	SEG382	SEG381	SEG380
			SEG381	SEG380	SEG383	SEG382	SEG384
			SEG382	SEG381	SEG380	SEG383	SEG384
			SEG383	SEG382	SEG381	SEG380	SEG384
			SEG384	SEG383	SEG382	SEG381	SEG380

Example for memory mapping: Let MX = 0, MY = 0, SL = 0, LC[7:6] = 10b (RR_{RRRR}-GG_{GGGG}-BB_{BBBB}, 64K-color), according to the data shown in the above table (R: 11111b, G: 111111b, B: 11111b):

1st Byte write-data: 11111111b2nd Byte write-data: 11111111b

For Black-and-White Display

Row Addresss	RAM			MY=0 SL=0	MY=1 SL=0
	Sn	Sn+1	Sn+2	SL=16	SL=16
00H				COM1	COM17
01H				COM2	COM18
02H				COM3	COM19
03H				COM4	COM20
04H				COM5	COM21
05H				COM6	COM22
06H				COM7	COM23
07H				COM8	COM24
08H				COM9	COM25
09H				COM10	COM26
0AH				COM11	COM27
0BH				COM12	COM28
0CH				COM13	COM29
0DH				COM14	COM30
0EH				COM15	COM31
0FH				COM16	COM32
10H				COM17	COM33
11H				COM18	COM34
12H				COM19	COM35
13H				COM20	COM36
14H				COM21	COM37
15H				COM22	COM38
16H				COM23	COM39
17H				COM24	COM40
18H				COM25	COM41
19H				COM26	COM42
1AH				COM27	COM43
1BH				COM28	COM44
1CH				COM29	COM45
88H				COM137	COM153
89H				COM138	COM154
8AH				COM139	COM155
8BH				COM140	COM156
8CH				COM141	COM157
8DH				COM142	COM158
8EH				COM143	COM159
8FH				COM144	COM160
90H				COM145	COM1
91H				COM146	COM2
92H				COM147	COM3
93H				COM148	COM4
94H				COM149	COM5
95H				COM150	COM6
96H				COM151	COM7
97H				COM152	COM8
98H				COM153	COM9
99H				COM154	COM10
9AH				COM155	COM11
9BH				COM156	COM12
9CH				COM157	COM13
9DH				COM158	COM14
9EH				COM159	COM15
9FH				COM160	COM16

M/X	0	1
SEG382	SEG1	
SEG383	SEG2	
SEG384	SEG3	
SEG379	SEG4	
SEG380	SEG5	
SEG5	SEG380	
SEG6	SEG381	
SEG1	SEG382	
SEG2	SEG383	
SEG3	SEG384	

Example for memory mapping:

Let MX = 0, MY = 0, SL = 0, LC[7:6] = 10b ($\boxed{Sn} \boxed{Sn+1} \boxed{Sn+2}$),then according to the data shown in the above table (1 $\boxed{0} \boxed{1} \boxed{0} \boxed{1} \boxed{0} \boxed{1}$),1-st byte write-data will be : 1 $\boxed{0} \boxed{0} \boxed{0} \boxed{0}$ b2-nd byte write-data will be : $\boxed{0} \boxed{1} \boxed{0} \boxed{0} \boxed{0}$ b

RESET & POWER MANAGEMENT

TYPES OF RESET

UC1698u has two different types of Reset:

Power-ON-Reset and *System-Reset*.

Power-ON-Reset is performed right after V_{DD} is connected to power. *Power-On-Reset* will first wait for about 150mS, depending on the time required for V_{DD} to stabilize, and then trigger the *System Reset*.

System Reset can also be activated by software command (that's Software Reset) or by connecting RST pin to ground (that's Pin Reset).

In the following discussions, Reset means Software Reset.

RESET STATUS

When UC1698u enters RESET sequence:

- Operation mode will be "Reset".
- All control registers are reset to default values. Refer to section *Control Registers* for details of their default values.

OPERATION MODES

UC1698u has three operating modes (OM):

Reset, Sleep, Normal.

Mode	Reset	Sleep	Normal
OM	00	10	11
Host Interface	Active	Active	Active
Clock	OFF	OFF	ON
LCD Drivers	OFF	OFF	ON
Charge Pump	OFF	OFF	ON
Draining Circuit	ON	ON	OFF

Table 4: Operating Modes

CHANGING OPERATION MODE

In addition to Power-ON-Reset, two commands will initiate OM transitions:

Set Display Enable, and *System Reset*.

When DC[2] is modified by *Set Display Enable*, OM will be updated automatically. There is no other action required to enter Sleep mode.

OM changes are synchronized with the edges of UC1698u internal clock. To ensure consistent system states, wait at least 10µS after *Set Display Enable* or *System Reset* command.

Action	Mode	OM
Reset command Power ON reset	Reset	00
Set Driver Enable to "0"	Sleep	10
Set Driver Enable to "1"	Normal	11

Table 5: OM changes

Both Reset mode and Sleep mode drain the charges stored in the external capacitors C_{B0} , C_{B1} , and C_L . When entering Reset mode or Sleep mode, the display drivers will be disabled.

The difference between Sleep mode and Reset mode is that, Reset mode clears all control registers and restores them to default values, while Sleep mode retains all the control registers values set by the user.

The difference between Software Reset and Pin Reset is that, Pin Reset does not drain the charge stored in the external capacitors C_{B0} , C_{B1} and C_L .

It is recommended to use Sleep Mode for Display OFF operations as UC1698u consumes very little energy in Sleep mode (typically under 2µA).

EXITING SLEEP MODE

UC1698u contains internal logic to check whether V_{LCD} and V_{BIAS} are ready before releasing COM and SEG drivers from their idle states. When exiting Sleep or Reset mode, COM and SEG drivers will not be activated until UC1698u internal voltage sources are restored to their proper values.

POWER-UP SEQUENCE

UC1698u power-up sequence is simplified by built-in "Power Ready" flags and the automatic invocation of *System-Reset* command after *Power-ON-Reset*.

System programmers are only required to wait 150 mS before the CPU starting to issue commands to UC1698u. No additional time sequences are required between enabling the charge pump, turning on the display drivers, writing to RAM or any other commands. However, while turning on V_{DD} , $V_{DD2/3}$ should be started not later than V_{DD} .

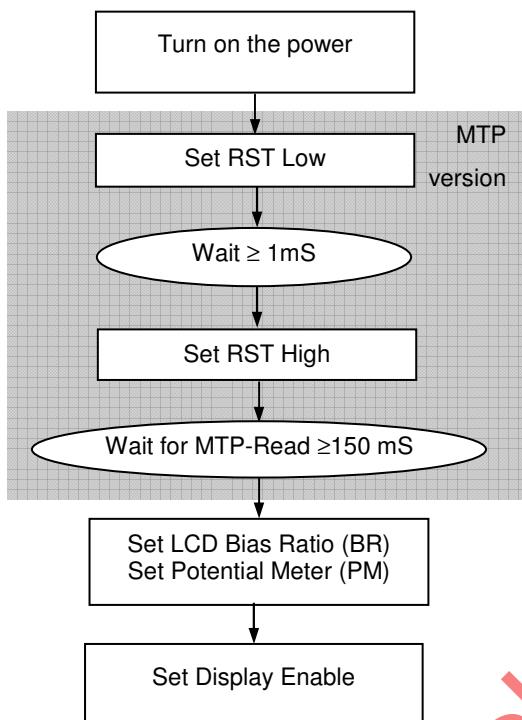


Figure 12: Reference Power-Up Sequence

POWER-DOWN SEQUENCE

To prevent the charge stored in capacitor C_L from causing abnormal residue horizontal line on display when V_{DD} is switched off, use Reset mode to enable the built-in draining circuit and discharge these capacitors.

When internal V_{LCD} is not used, UC1698u will *NOT* drain V_{LCD} during RESET. System designers need to make sure external V_{LCD} source is properly drained off before turning off V_{DD} .

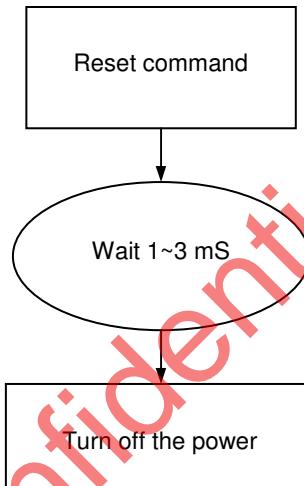


Figure 13: Reference Power-Down Sequence

Delay allowance between V_{DD} and $V_{DD2/3}$ is illustrated as Figure 14.

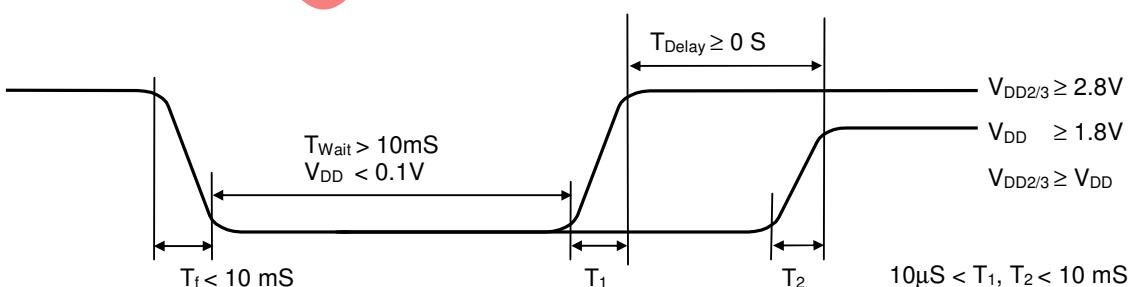


Figure 14: Delay allowance and Power Off-On Sequence

SAMPLE POWER MANAGEMENT COMMAND SEQUENCES

The following tables are examples of command sequence for power-up, power-down and display ON/OFF operations. These are only to demonstrate some “*typical, generic*” scenarios. Designers are encouraged to study related sections of the datasheet and find out what the best parameters and control sequences are for their specific design needs.

Type Required: These items are required
 Customized: These items are not necessary if customer parameters are the same as default
 Advanced: We recommend new users to skip these commands and use default values.
 Optional: These commands depend on what users want to do.

C/D The type of the interface cycle. It can be either Command (0) or Data (1)
W/R The direction of dataflow of the cycle. It can be either Write (0) or Read (1).

POWER-UP

Type	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Chip action	Comments
R	-	-	-	-	-	-	-	-	-	-	Turn on V _{DD} and V _{DD2/3}	Wait until V _{DD} , V _{DD2/3} are stable
R	-	-	-	-	-	-	-	-	-	-	Set RST pin Low	Wait 1mS after RST is Low
R	-	-	-	-	-	-	-	-	-	-	Set RST pin High	
R	-	-	-	-	-	-	-	-	-	-	Automatic Power-ON Reset	Wait 150mS
C	0	0	0	0	1	0	0	1	#	#	Set Temp. Compensation	Set up LCD format specific parameters, MX, MY, etc.
C	0	0	1	1	0	0	0	#	#	#	Set LCD Mapping	
A	0	0	1	0	1	0	0	0	#	#	Set Line Rate	Fine tune for power, flicker, contrast, and shading.
C	0	0	1	1	0	1	0	1	#	#	Set Color Mode	
C	0	0	1	1	1	0	1	0	#	#	Set LCD Bias Ratio	LCD specific operating voltage setting
R	0	0	1	0	0	0	0	0	0	1	Set V _{BIAS} Potentiometer	LCD specific operating voltage setting
O	1	0	#	#	#	#	#	#	#	#	Write display RAM	
O	Set up display image	
O		
O	1	0	#	#	#	#	#	#	#	#		
R	0	0	1	0	1	0	1	1	1	1	Set Display Enable	

* For power saving mode, please refer to UltraChip document “03-OTS-003 Power Saving Mode Disable Application Note version A”.

POWER-DOWN

Type	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Chip action	Comments
R	0	0	1	1	1	0	0	0	1	0	System Reset	
R	-	-	-	-	-	-	-	-	-	-	Draining capacitor	Wait ~3mS before V _{DD} OFF

DISPLAY-OFF

Type	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Chip action	Comments
R	0	0	1	0	1	0	1	1	1	0	Set Display Disable	
C	1	0	#	#	#	#	#	#	#	#	Write display RAM	Set up display image (Image update is optional. Data in the RAM is retained through the SLEEP state.)
C		
C		
C	1	0	#	#	#	#	#	#	#	#		
R	0	0	1	0	1	0	1	1	1	1	Set Display Enable	

MULTI-TIME PROGRAM NV MEMORY

OVERVIEW

MTP feature is available for UC1698u such that LCM makers can record an PM offset value in non-volatile memory cells, which can then be used to adjust the effective V_{LCD} value, in order to achieve high level of consistency for LCM contrast across all shipments.

To accomplish this purpose, three operations are supported by UC1698u:

MTP-Erase, MTP-Program, MTP-Read.

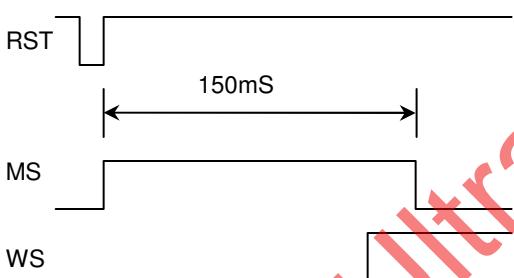
MTP-Program requires an external power source supplied to TST4 pin. MTP allows to program at least 10 times and should be performed only by the LCM makers.

MTP-Read is facilitated by the internal DC-DC converter built-in on UC1698u, no external power source is required, and it is performed automatically after hardware RESET (power-ON or pin RESET).

OPERATION FOR THE SYSTEM USERS

For the MTP version of UC1698u, the content of the NV memory will be read automatically after the power-on and hardware pin RESET. There is no user intervention or external power source required. When set up properly, the V_{LCD} will be fine tuned to achieve high level of consistency for the LCM contrast.

The MTP-READ is a relatively slow process and the time required can vary quite a bit. For a successful MTP-READ operation, the MS and WS bits in the *Read Status* commands will exhibit the following waveforms.



As illustrated above, the {MS, WS} will go through a $\{0,0\} \Rightarrow \{1,0\} \Rightarrow \{1,1\} \Rightarrow \{0,1\}$ transition. When the {MS, WS} = {0, 1} state is reached, it means the LCM is ready to be turned on.

Although user can use *Read Status* command in a polling loop to make sure {MS, WS} = {0, 1} before proceeding with the normal operations, however, it may be simpler to just issue *Set Display Enable* command every 0.5~2 seconds, repeatedly, together with other LCM optimization settings, such as BR, CEN, TC, etc.

The above "Periodical re-initializing" approach is also an effective safeguard against accidental display off events such as

- ESD strikes
- Mechanical shocks causing LCM connector to malfunction temporarily

HARDWARE VS. SOFTWARE RESET

The auto-MTP-READ is only performed for hardware RESET (power-ON and RST pin), but not for software *RESET* command. This enables the ICs to turn on display faster without the delay caused by MTP-READ.

It is recommended to use software *RESET* for normal operation control purpose while use power down and hardware *RESET* only during the event of power up.

OPERATION FOR THE LCM MAKERS

Always ERASE the MTP NV memory cells, before starting the Write process.

MTP OPERATION FOR LCM MAKERS

1. High voltage supply and timer setting

In MTP Program operation, two different high voltages are needed. In chip design, one high voltage is generated by internal charge pump (V_{LCD}), the other high voltage must be input from TST4 by external voltage source.

V_{LCD} value is controlled by register MTP3 and MTP2. The default values of these two registers are appropriate for most applications.

External TST4 power source is required for MTP Program operation. MTP Programming speed depends on the TST4 voltage. Considering the ITO trace resistance in COG modules, it is recommended to program the MTP cells one at a time, so that the required 10V at TST4 can be maintained with proper consistency.

No external power source is required for MTP Erase and Read operation. For these MTP operations, TST4 should be open, or connected to V_{DD3} .

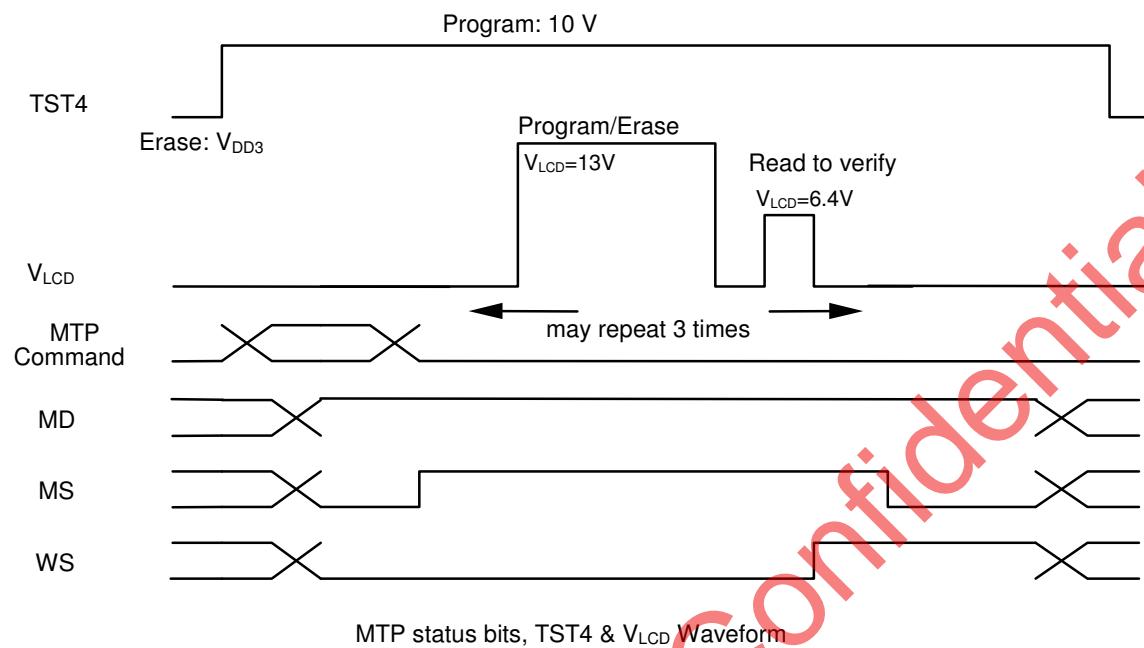
	V_{LCD}	TST4 (external input)
Program	MTP2 : 26h (13V)	10V (1mA per bit)
Erase	MTP2 : 26h (13V)	Floating or V_{DD3}
Read	MTP1 : 16h (6.4V)	Floating or V_{DD3}

Note:

1. Do Erase before Program and program one bit at a time.
2. When doing MTP Program or Erase, it's required to use $V_{DD2/3} \geq 3.0V$

2. Read MTP status bits

With normal Get Status method (CD=0, W/R=1), MTP operation status can be monitored in the real time. There are 3 status bits (WS, MD, MS) in status register. MTP control circuit will read to verify if the operation (program, erase) success or not. If the operation succeeded, and current operation will be ended with WS=1. If it failed, last operation will be automatically retried two more times. If it fails 3 times, WS will be set to 0 and the operation is aborted. MD is MTP ID, which is either 1 for MTP IC. No transition.



3. MTP CELL VALUE USAGE

There are 9 MTP cell bits. They are divided into two groups for different purpose.

MTP[6:0] : V_{LCD} Trim

When PMO[6]=1: PM with trim = PM - PMO[5:0]
When PMO[6]=0: PM with trim = PM + PMO[5:0]

MTPID[1:0]: For LCM manufacturer's configuration.

MTP COMMAND SEQUENCE SAMPLE CODES

The following tables are examples of command sequence for MTP Program and Erase operations. These are only to demonstrate some “*typical, generic*” scenarios. Designers are encouraged to study related sections of the datasheet and find out what the best parameters and control sequences are for their specific design needs.

MTP operations (Erase, Program, Read) and Set Display ON is mutual exclusive. There is no harm done to the IC or the LCM if this is violated. However, the violating commands will be ignored.

Type Required: These items are required

Customized: These items are not necessary if customer parameters are the same as default

Advanced: We recommend new users to skip these commands and use default values.

Optional: These commands depend on what users want to do.

C/D The type of the interface cycle. It can be either Command (0) or Data (1)

W/R The direction of dataflow of the cycle. It can be either Write (0) or Read (1).

(1) MTP Program Sample Code

Type	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Chip Action	Comments
R	0	0	1	0	1	0	0	0	1	1	Set Line Rate	Set LC[4:3]=11b
R	0	0	1	1	1	1	0	1	0	0	Set V _{MTP1} Potentiometer	Set MTP V _{LCD}
R	0	0	0	0	0	1	0	1	1	0		MTP1: 16h(6.4V)
R	0	0	1	1	1	1	0	1	0	1	Set V _{MTP2} Potentiometer	Set MTP V _{LCD}
R	0	0	0	0	1	0	0	1	1	0		MTP2: 26h(13V)
R	0	0	1	1	1	1	0	1	1	0	Set MTP Write Timer	Set MTP Timer
R	0	0	0	1	1	0	0	1	1	0		MTP3: 66h(200mS)
R	0	0	1	1	1	1	0	1	1	1	Set MTP Read Timer	Set MTP Timer
R	0	0	0	0	0	0	1	0	0	0		MTP4: 08h(10mS)
R	0	0	1	0	1	1	1	0	0	1	Set MTP Write Mask	Set MTP Bit Mask
C	0	0	0	0	0	0	0	0	0	1	MTPM MTPM1	Ex: To program MTPM[0] to be 1, set the value to 00000001b *
R	-	-	-	-	-	-	-	-	-	-		Apply TST4 voltage Program: 10 V
R	0	0	1	0	1	1	1	0	0	0	Set MTP Control	Set MTPC[3]=1
R	0	0	-	-	0	0	1	0	1	1		Set MTPC[2:0]=011
R	0	1	-	-	-	-	-	WS	-	MS	Get Status & PM	Check MTP Status until MS=0 and WS=1
R												Remove TST4 voltage
R											V _{DD} =0V	Power OFF

* It is recommended that users program one bit at a time.

(2) MTP Erase Sample Code

Type	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Chip action	Comments
R	0	0	1	0	1	0	0	0	1	1	Set Line Rate	Set LC[4:3]=11b
R	0	0	1	1	1	1	0	1	0	0	Set V _{MTP1} Potentiometer	Set MTP V _{LCD} MTP1: 16h(6.4V)
R	0	0	0	0	0	1	0	1	1	0	Set V _{MTP2} Potentiometer	Set MTP V _{LCD} MTP2: 26h (13V)
R	0	0	1	1	1	1	0	1	0	1	Set MTP Write Timer	Set MTP Timer MTP3: 66h (200mS)
R	0	0	0	1	1	0	0	1	1	0	Set MTP Read Timer	Set MTP Timer MTP4: 08h (10ms)
R	0	0	1	0	1	1	1	0	1	1	Set MTP Write Mask	Set MTP Bit Mask
C	0	0	0	0	0	0	1	1	1	1	MTPM MTPM1	Ex: To erase MTPM[3:0], set the value to 00001111b
R	0	0	1	0	1	1	1	0	0	0	Set MTP Control	Set MTPC[3]=1 Set MTPC[2:0]=010
R	0	1	-	-	0	0	1	0	1	0	Get Status & PM	Check MTP Status until MS=0, WS=1
R											V _{DD} =0V	Power OFF

Note: It is recommended that users clear all the bits to be programmed.

ESD CONSIDERATION

UC1600 series products usually are provided in bare die format to customers. This makes the product particularly sensitive to ESD damage during handling and manufacturing process. It is therefore highly recommended that LCM makers strictly follow the "JESD 625-A Requirements for Handling Electrostatic-Discharge-Sensitive (ESDS) Devices" when manufacturing LCM.

The following pins in UC1698u require special "ESD Sensitivity" consideration in particular:

Test Mode	Machine Mode		Human Body Mode	
	V _{DD}	V _{SS}	V _{DD}	V _{SS}
LCD Driver	200	200	2000	2000
LCM Interface	300	300	3000	3000
TST1/2/4	200	200	2000	2000
LCM HV pin/ Test pin	C _B pins	200	2000	2000
	V _{LCDIN}	200	2000	2000
	V _{LCDOUT}	200	2000	2000
PWR / GND	--	300	--	3000

According to UltraChip's Mass Production experiences, the ESD tolerance conditions are believed to be very stable and can produce high yield in multiple customer sites. However, special care is still required during handling and manufacturing process to avoid unnecessary yield loss due to ESD damages.

ABSOLUTE MAXIMUM RATINGS

In accordance with IEC134, Note 1 and 2

Symbol	Parameter	Min.	Max.	Unit
V _{DD}	Logic Supply voltage	-0.3	+4.0	V
V _{DD2}	LCD Generator Supply voltage	-0.3	+4.0	V
V _{DD3}	Analog Circuit Supply voltage	-0.3	+4.0	V
V _{DD2/3-V_{DD}}	Voltage difference between V _{DD} and V _{DD2/3}	--	1.6	V
V _{LCD}	LCD Driving voltage (-25°C ~ +75°C)	-0.3	+19.8	V
V _{IN}	Digital input signal	-0.4	V _{DD} + 0.5	V
T _{OPR}	Operating temperature range	-30	+85	°C
		-40 ⁽³⁾	+85	°C
T _{STR}	Storage temperature	-55	+125	°C

NOTE:

- (1) V_{DD} is based on V_{SS} = 0V
- (2) Stress beyond ranges listed above may cause permanent damages to the device.
- (3) Need to keep V_{LCD} under 17.5V at -40°C.

SPECIFICATIONS**DC CHARACTERISTICS**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{DD}	Supply for digital circuit		1.65		3.465	V
$V_{DD2/3}$	Supply for bias & pump		2.7		3.465	V
V_{LCD}	Charge pump output	$V_{DD2/3} = 2.8V, 25^{\circ}C$		15.2	18	V
		$V_{DD2/3} = 2.8V, -40^{\circ}C$		15.2	17.5	V
V_D	LCD data voltage	$V_{DD2/3} = 2.8V, 25^{\circ}C$	1.09		1.95	V
V_{IL}	Input logic LOW				$0.2V_{DD}$	V
V_{IH}	Input logic HIGH		0.8 V_{DD}			V
V_{OL}	Output logic LOW				$0.2V_{DD}$	V
V_{OH}	Output logic HIGH		0.8 V_{DD}			V
I_{IL}	Input leakage current				1.5	μA
I_{SB}	Standby current	$V_{DD} = V_{DD2/3} = 3.3V$, Temp = $85^{\circ}C$			50	μA
C_{IN}	Input capacitance		5		10	PF
C_{OUT}	Output capacitance		5		10	PF
$R_{ON(SEG)}$	SEG output impedance	$V_{LCD} = 16.5V$		850	1100	Ω
$R_{ON(COM)}$	COM output impedance	$V_{LCD} = 16.5V$		950	1100	Ω
f_{LINE}	Average line rate	LC[4:3] = 10b, $25^{\circ}C$	-10%	37.0	+10%	Klps

POWER CONSUMPTION

$V_{DD} = 2.7\text{ V}$,
 $V_{LCD} = 16.5\text{ V}$,
Mux Rate = 160,
 $C_B = 2.2\text{ }\mu F$,
N-line inversion = 31 lines

Bias Ratio = 12,
Line Rate = 10b,
Bus mode = 6800,
Temperature = $25^{\circ}C$,
Color Mode = 64K color mode,

PM = 64,
Panel Loading (PC[1:0]) = 0b,
 $C_L = 330\text{ nF}$,
MTP=00 H,
All HV outputs are open circuit.

Display Pattern	Conditions	Typ.	Max.	Unit
All-Pixel-OFF	Bus = idle	1764	2470	μA
2-pixel checker	Bus = idle	2468	3455	μA
None	Reset (stand-by current)	<1	5	μA

AC CHARACTERISTICS

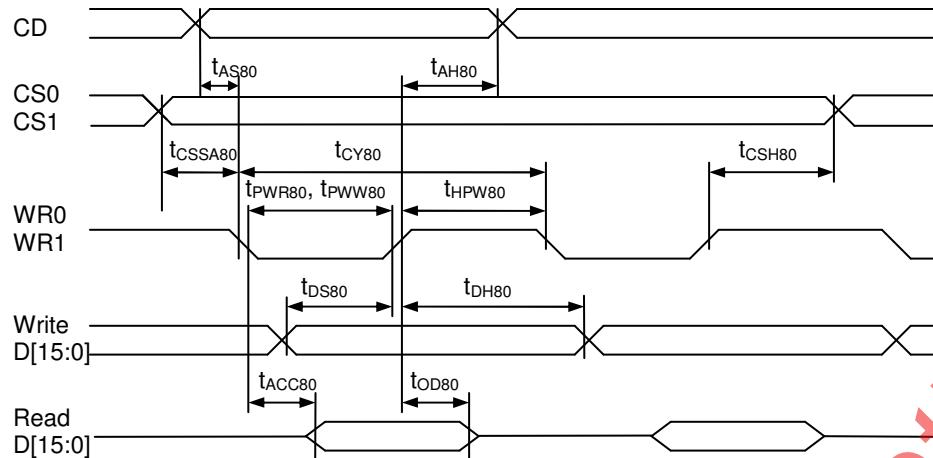


FIGURE 15: Parallel Bus Timing Characteristics (for 8080 MCU)

Symbol	Signal	Description	Condition	Min.	Max.	Unit
(2.5V ≤ V _{DD} ≤ 3.3V, Ta= -40 to +85°C)						(Read / Write)
t _{AS80} t _{AH80}	CD	Address setup time Address hold time		0 10	—	nS
t _{CY80}		System cycle time	16-bit bus 8-bit bus	200 / 160 130 / 110 / 120	—	nS
t _{PWR80} / t _{PWW80}	WR1 / WR0	Pulse width	16-bit bus 8-bit bus	85 / 65 50 / 40 / 45	—	nS
t _{HPW80}	WR0, WR1	High pulse width	16-bit bus 8-bit bus	85 / 65 50 / 40 / 45	—	nS
t _{DS80} t _{DH80}	D15~D0	Data setup time Data hold time		30 10	—	nS
t _{ACC80} t _{OD80}		Read access time Output disable time	C _L = 100pF	— 15	80 30	nS
t _{CSA80} t _{CSH80}	CS1/CS0	Chip select setup time		5 15	—	nS
(1.65V ≤ V _{DD} < 2.5V, Ta= -40 to +85°C)						
t _{AS80} t _{AH80}	CD	Address setup time Address hold time		0 10	—	nS
t _{CY80}		System cycle time	16-bit bus 8-bit bus	350 / 300 210 / 175 / 250	—	nS
t _{PWR80} / t _{PWW80}	WR1 / WR0	Pulse width	16-bit bus 8-bit bus	160 / 135 90 / 73 / 110	—	nS
t _{HPW80}	WR0, WR1	High pulse width	16-bit bus 8-bit bus	160 / 135 90 / 72 / 110	—	nS
t _{DS80} t _{DH80}	D15~D0	Data setup time Data hold time		60 10	—	nS
t _{ACC80} t _{OD80}		Read access time Output disable time	C _L = 100pF	— 30	140 60	nS
t _{CSA80} t _{CSH80}	CS1/CS0	Chip select setup time		10 20	—	nS

Note: The rising time and the falling time are stipulated to be equal to or less than 15nS.

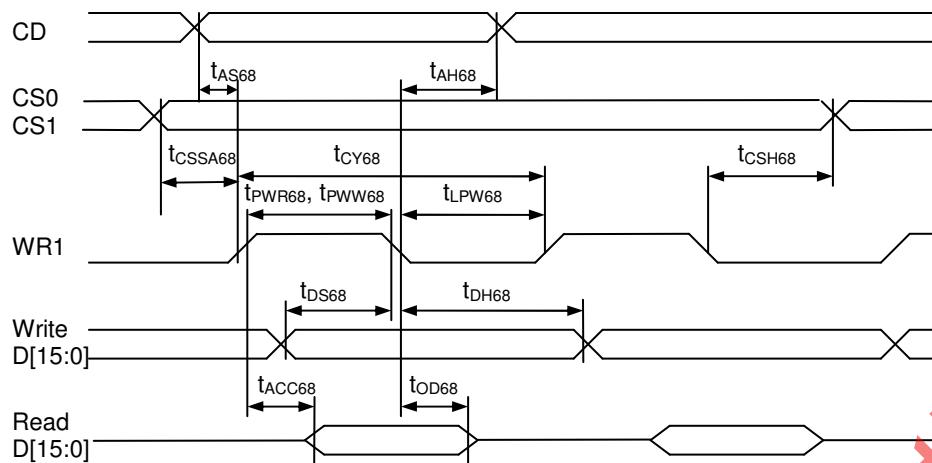


FIGURE 16: Parallel Bus Timing Characteristics (for 6800 MCU)

Symbol	Signal	Description	Condition	Min.	Max.	Unit
(2.5V ≤ V _{DD} ≤ 3.3V, Ta= -40 to +85 [°] C)						(Read / Write)
t _{AS68} t _{AH68}	CD	Address setup time Address hold time		0 10	—	nS
t _{CY68}		System cycle time	16-bit bus 8-bit bus	200 / 160 130 / 110 / 120	—	nS
t _{PWR68} / t _{PWW68}	WR1	Pulse width	16-bit bus 8-bit bus	85 / 65 50 / 40 / 45	—	nS
t _{LPW68}		Low pulse width	16-bit bus 8-bit bus	85 / 65 50 / 40 / 45	—	nS
t _{DS68} t _{DH68}	D15~D0	Data setup time Data hold time		30 10	—	nS
t _{ACC68} t _{OD68}		Read access time Output disable time	C _L = 100pF	— 15	80 30	nS
t _{CSA68} t _{CSH68}	CS1/CS0	Chip select setup time		5 15	—	nS
(1.65V ≤ V _{DD} < 2.5V, Ta= -40 to +85 [°] C)						
t _{AS68} t _{AH68}	CD	Address setup time Address hold time		0 10	—	nS
t _{CY68}		System cycle time	16-bit bus 8-bit bus	350 / 300 210 / 175 / 250	—	nS
t _{PWR68} / t _{PWW68}	WR1	Pulse width	16-bit bus 8-bit bus	160 / 135 90 / 73 / 110	—	nS
t _{LPW68}		Low pulse width	16-bit bus 8-bit bus	160 / 135 90 / 72 / 110	—	nS
t _{DS68} t _{DH68}	D15~D0	Data setup time Data hold time		60 10	—	nS
t _{ACC68} t _{OD68}		Read access time Output disable time	C _L = 100pF	- 30	140 60	nS
t _{CSA68} t _{CSH68}	CS1/CS0	Chip select setup time		10 20	—	nS

Note: The rising time and the falling time are stipulated to be equal to or less than 15nS.

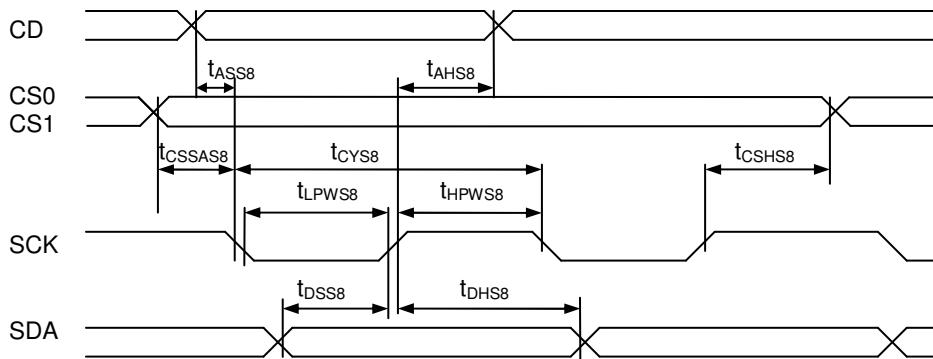


FIGURE 17: Serial Bus Timing Characteristics (for S8/S8uc)

Symbol	Signal	Description	Condition	Min.	Max.	Unit
(2.5V ≤ V _{DD} ≤ 3.3V, Ta= -40 to +85°C)						(Read / Write)
t _{ASS8}	CD	Address setup time		0	—	nS
t _{AHS8}		Address hold time		10	—	nS
t _{CSSAS8}	CS1/CS0	Chip select setup time		5	—	nS
t _{CYS8}	SCK	System cycle time		70	—	nS
t _{LPWS8}		Low pulse width		20	—	nS
t _{HPWS8}		High pulse width		20	—	nS
t _{DSS8}	SDA	Data setup time		15	—	nS
t _{DHS8}		Data hold time		10	—	nS
(1.65V ≤ V _{DD} < 2.5V, Ta= -40 to +85°C)						
t _{ASS8}	CD	Address setup time		0	—	nS
t _{AHS8}		Address hold time		10	—	nS
t _{CSSAS8}	CS1/CS0	Chip select setup time		10	—	nS
t _{CYS8}	SCK	System cycle time		105	—	nS
t _{LPWS8}		Low pulse width		37	—	nS
t _{HPWS8}		High pulse width		38	—	nS
t _{DSS8}	SDA	Data setup time		30	—	nS
t _{DHS8}		Data hold time		10	—	nS

Note: The rising time and the falling time are stipulated to be equal to or less than 15nS.

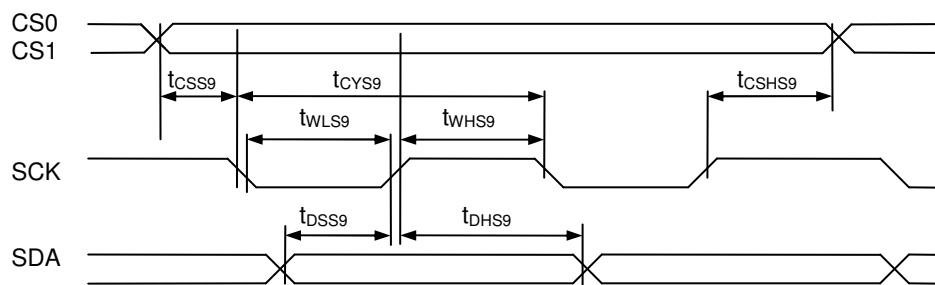


FIGURE 18: Serial Bus Timing Characteristics (for S9)

Symbol	Signal	Description	Condition	Min.	Max.	Units
(2.5V ≤ V _{DD} ≤ 3.3V, Ta= -40 to +85°C)						(Read / Write)
t _{CSAS9} t _{CSHS9}	CS1/CS0	Chip select setup time		5 15		nS
t _{CYS9} t _{LPWS9} t _{HPWS9}	SCK	System cycle time Low pulse width High pulse width		70 20 20	— — —	nS
t _{DSS9} t _{DHS9}	SDA	Data setup time Data hold time		15 10	— —	nS
(1.65V ≤ V _{DD} < 2.5V, Ta= -40 to +85°C)						
t _{CSAS9} t _{CSHS9}	CS1/CS0	Chip select setup time		10 20		nS
t _{CYS9} t _{LPWS9} t _{HPWS9}	SCK	System cycle time Low pulse width High pulse width		105 37 38	— — —	nS
t _{DSS9} t _{DHS9}	SDA	Data setup time Data hold time		30 10	— —	nS

Note: The rising time and the falling time are stipulated to be equal to or less than 15nS.

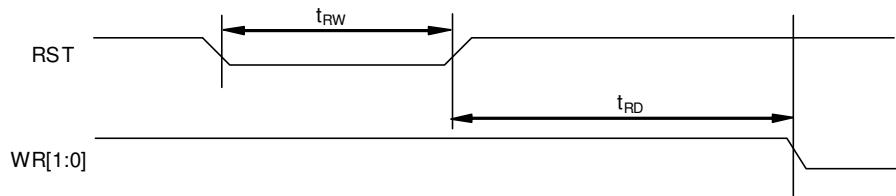


FIGURE 19: Reset Characteristics

Symbol	Signal	Description	Condition	Min.	Max.	Units
(1.65V $\leq V_{DD} \leq$ 3.3V, Ta= -40 to +85°C)						
t_{RW}	RST	Reset low pulse width		3	-	μS
t_{RD}	RST, WR	Reset to WR pulse delay		10	-	mS

Note:

For each mode, the signal's rising time (tr) and falling time (tf) are stipulated to be equal to or less than 15nS each.



PHYSICAL DIMENSIONS

DIE SIZE:
13380 μ M x 1712 μ M \pm 50 μ M

DIE THICKNESS:
0.4mm \pm 0.02mm

BUMP HEIGHT:
15 μ M
(12 μ M \pm 3 μ M also available)
(H_{MAX}-H_{MIN}) within die < 2 μ M

COM/SEG SIZE:
17.5 x 115 μ M² (Typ.)

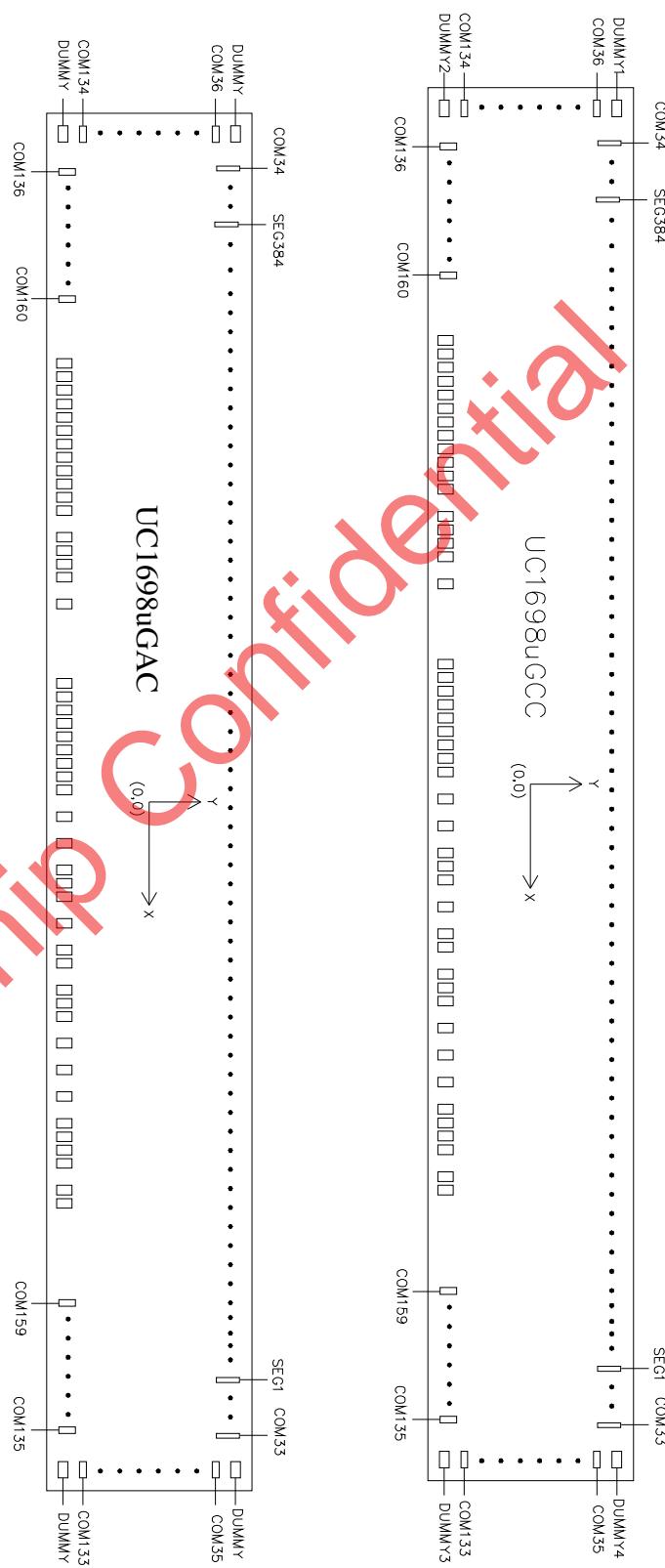
BUMP PITCH:
COM: 31 μ M (Typ.)
SEG: 31 μ M (Typ.)

BUMP SPACE:
SEG/COM: 13.5 μ M (Typ.)
11.5 μ M (Min.)

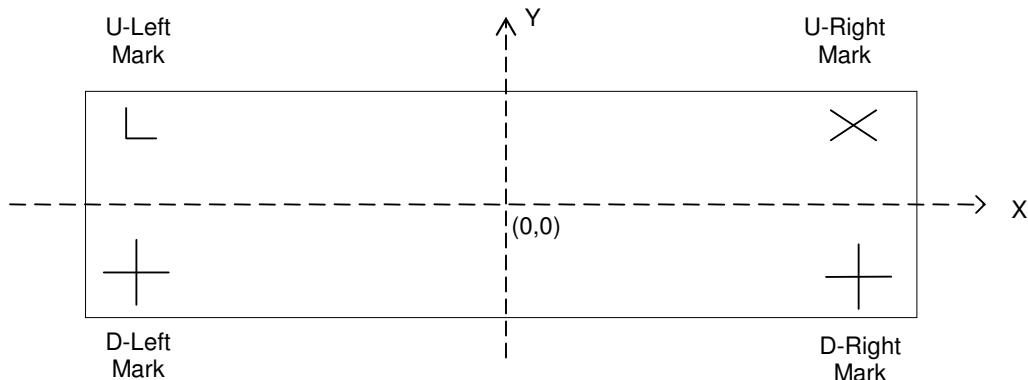
COORDINATE ORIGIN:
Chip center

PAD REFERENCE:
Pad center

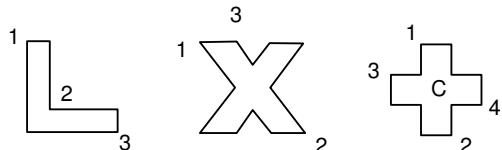
(Drawing and coordinates are for the
Circuit/Bump view.)



ALIGNMENT MARK INFORMATION



SHAPE OF THE ALIGNMENT MARK:



NOTE:

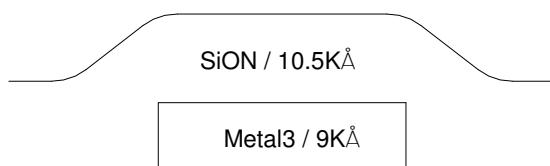
Alignment mark is on Metal3 under Passivation.

The "x" and "+" marks are symmetrical both horizontally and vertically.

COORDINATES:

	U-Left Mark (L)		U-Right Mark (X)	
	X	Y	X	Y
1	-6479.35	593.22	6439.801	593.22
2	-6463.73	568.72	6479.801	553.22
3	-6439.35	553.22	6449.801	593.22
	D-Left Mark (+)		D-Right Mark (+)	
	X	Y	X	Y
1	-6003	-711.6	5983	-711.6
2	-5983	-796.6	6003	-796.6
3	-6035.5	-744.1	5950.5	-744.1
4	-5950.5	-764.1	6035.5	-764.1
C	-5993	-754.1	5993	-754.1

TOP METAL AND PASSIVATION:



FOR MTP PROCESS CROSS-SECTION

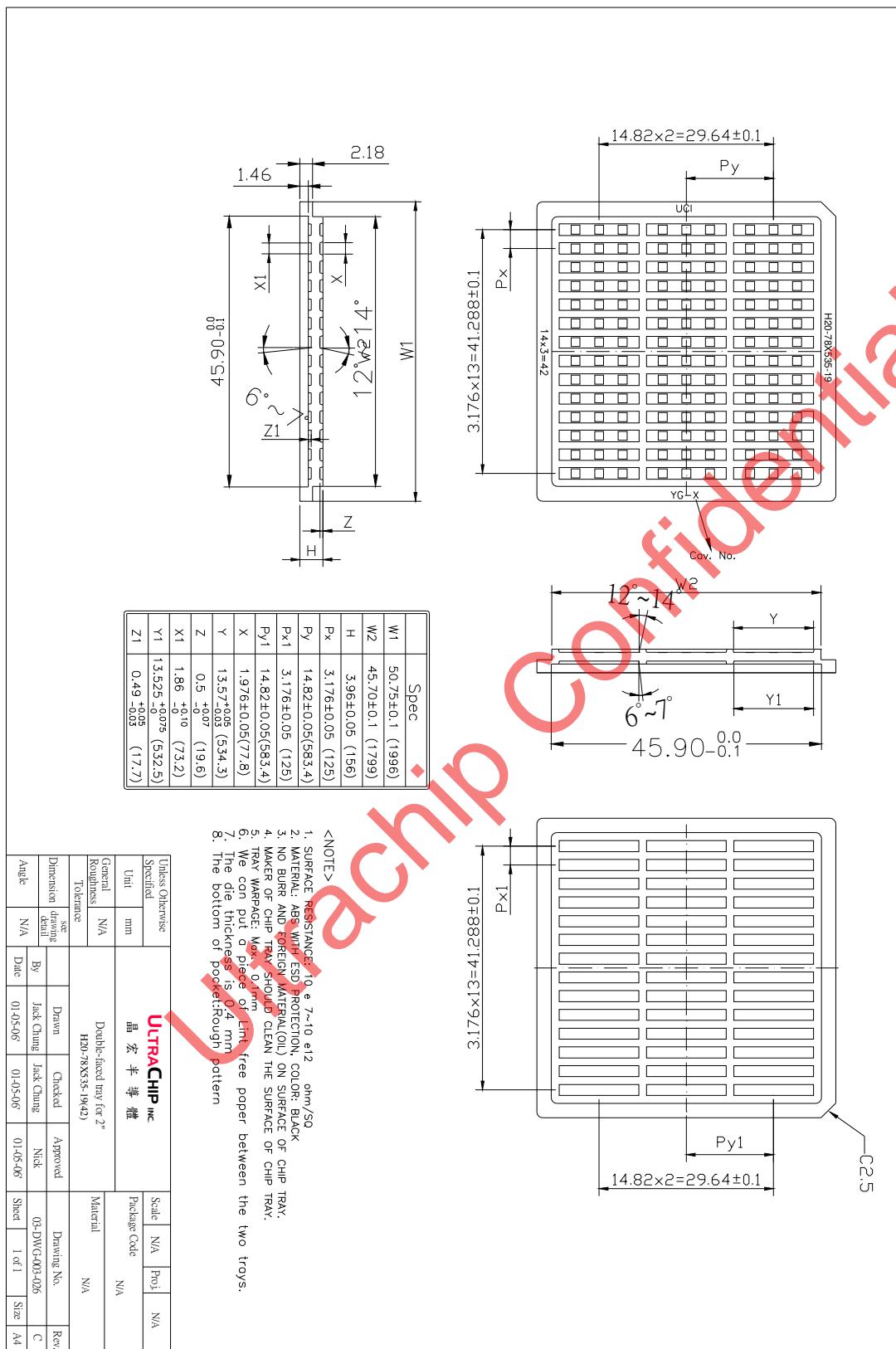
#	Pad	X	Y	W	H
605	SEG353	-4975.5	748.1	17.5	115
606	SEG354	-5006.5	748.1	17.5	115
607	SEG355	-5037.5	748.1	17.5	115
608	SEG356	-5068.5	748.1	17.5	115
609	SEG357	-5099.5	748.1	17.5	115
610	SEG358	-5130.5	748.1	17.5	115
611	SEG359	-5161.5	748.1	17.5	115
612	SEG360	-5192.5	748.1	17.5	115
613	SEG361	-5223.5	748.1	17.5	115
614	SEG362	-5254.5	748.1	17.5	115
615	SEG363	-5285.5	748.1	17.5	115
616	SEG364	-5316.5	748.1	17.5	115
617	SEG365	-5347.5	748.1	17.5	115
618	SEG366	-5378.5	748.1	17.5	115
619	SEG367	-5409.5	748.1	17.5	115
620	SEG368	-5440.5	748.1	17.5	115
621	SEG369	-5471.5	748.1	17.5	115
622	SEG370	-5502.5	748.1	17.5	115
623	SEG371	-5533.5	748.1	17.5	115
624	SEG372	-5564.5	748.1	17.5	115
625	SEG373	-5595.5	748.1	17.5	115
626	SEG374	-5626.5	748.1	17.5	115
627	SEG375	-5657.5	748.1	17.5	115
628	SEG376	-5688.5	748.1	17.5	115
629	SEG377	-5719.5	748.1	17.5	115
630	SEG378	-5750.5	748.1	17.5	115
631	SEG379	-5781.5	748.1	17.5	115
632	SEG380	-5812.5	748.1	17.5	115
633	SEG381	-5843.5	748.1	17.5	115
634	SEG382	-5874.5	748.1	17.5	115
635	SEG383	-5905.5	748.1	17.5	115
636	SEG384	-5936.5	748.1	17.5	115
637	COM2	-5967.5	748.1	17.5	115
638	COM4	-5998.5	748.1	17.5	115
639	COM6	-6029.5	748.1	17.5	115
640	COM8	-6060.5	748.1	17.5	115
641	COM10	-6091.5	748.1	17.5	115
642	COM12	-6122.5	748.1	17.5	115
643	COM14	-6153.5	748.1	17.5	115
644	COM16	-6184.5	748.1	17.5	115
645	COM18	-6215.5	748.1	17.5	115
646	COM20	-6246.5	748.1	17.5	115
647	COM22	-6277.5	748.1	17.5	115
648	COM24	-6308.5	748.1	17.5	115
649	COM26	-6339.5	748.1	17.5	115
650	COM28	-6370.5	748.1	17.5	115
651	COM30	-6401.5	748.1	17.5	115
652	COM32	-6432.5	748.1	17.5	115
653	COM34	-6463.5	748.1	17.5	115

(The values of the x-coordinate and the y-coordinate in the table are after rounded.)

#	Pad	X	Y	W	H
235	COM<115>	6579.75	-480.5	115	17.5
236	COM<113>	6579.75	-449.5	115	17.5
237	COM<111>	6579.75	-418.5	115	17.5
238	COM<109>	6579.75	-387.5	115	17.5
239	COM<107>	6579.75	-356.5	115	17.5
240	COM<105>	6579.75	-325.5	115	17.5
241	COM<103>	6579.75	-294.5	115	17.5
242	COM<101>	6579.75	-263.5	115	17.5
243	COM<99>	6579.75	-232.5	115	17.5
244	COM<97>	6579.75	-201.5	115	17.5
245	COM<95>	6579.75	-170.5	115	17.5
246	COM<93>	6579.75	-139.5	115	17.5
247	COM<91>	6579.75	-108.5	115	17.5
248	COM<89>	6579.75	-77.5	115	17.5
249	COM<87>	6579.75	-46.5	115	17.5
250	COM<85>	6579.75	-15.5	115	17.5
251	COM<83>	6579.75	15.5	115	17.5
252	COM<81>	6579.75	46.5	115	17.5
253	COM<79>	6579.75	77.5	115	17.5
254	COM<77>	6579.75	108.5	115	17.5
255	COM<75>	6579.75	139.5	115	17.5
256	COM<73>	6579.75	170.5	115	17.5
257	COM<71>	6579.75	201.5	115	17.5
258	COM<69>	6579.75	232.5	115	17.5
259	COM<67>	6579.75	263.5	115	17.5
260	COM<65>	6579.75	294.5	115	17.5
261	COM<63>	6579.75	325.5	115	17.5
262	COM<61>	6579.75	356.5	115	17.5
263	COM<59>	6579.75	387.5	115	17.5
264	COM<57>	6579.75	418.5	115	17.5
265	COM<55>	6579.75	449.5	115	17.5
266	COM<53>	6579.75	480.5	115	17.5
267	COM<51>	6579.75	511.5	115	17.5
268	COM<49>	6579.75	542.5	115	17.5
269	COM<47>	6579.75	573.5	115	17.5
270	COM<45>	6579.75	604.5	115	17.5
271	COM<43>	6579.75	635.5	115	17.5
272	COM<41>	6579.75	666.5	115	17.5
273	COM<39>	6579.75	697.5	115	17.5
274	COM<37>	6579.75	728.5	115	17.5
275	COM<35>	6579.75	759.5	115	17.5
276	DUMMY4	6579.75	792.5	115	21.5
277	COM<33>	6463.5	748.1	17.5	115
278	COM<31>	6432.5	748.1	17.5	115
279	COM<29>	6401.5	748.1	17.5	115
280	COM<27>	6370.5	748.1	17.5	115
281	COM<25>	6339.5	748.1	17.5	115
282	COM<23>	6308.5	748.1	17.5	115
283	COM<21>	6277.5	748.1	17.5	115
284	COM<19>	6246.5	748.1	17.5	115
285	COM<17>	6215.5	748.1	17.5	115
286	COM<15>	6184.5	748.1	17.5	115
287	COM<13>	6153.5	748.1	17.5	115
288	COM<11>	6122.5	748.1	17.5	115
289	COM<9>	6091.5	748.1	17.5	115
290	COM<7>	6060.5	748.1	17.5	115
291	COM<5>	6029.5	748.1	17.5	115
292	COM<3>	5998.5	748.1	17.5	115
293	COM<1>	5967.5	748.1	17.5	115

#	Pad	X	Y	W	H
294	SEG<1>	5936.5	748.1	17.5	115
295	SEG<2>	5905.5	748.1	17.5	115
296	SEG<3>	5874.5	748.1	17.5	115
297	SEG<4>	5843.5	748.1	17.5	115
298	SEG<5>	5812.5	748.1	17.5	115
299	SEG<6>	5781.5	748.1	17.5	115
300	SEG<7>	5750.5	748.1	17.5	115
301	SEG<8>	5719.5	748.1	17.5	115
302	SEG<9>	5688.5	748.1	17.5	115
303	SEG<10>	5657.5	748.1	17.5	115
304	SEG<11>	5626.5	748.1	17.5	115
305	SEG<12>	5595.5	748.1	17.5	115
306	SEG<13>	5564.5	748.1	17.5	115
307	SEG<14>	5533.5	748.1	17.5	115
308	SEG<15>	5502.5	748.1	17.5	115
309	SEG<16>	5471.5	748.1	17.5	115
310	SEG<17>	5440.5	748.1	17.5	115
311	SEG<18>	5409.5	748.1	17.5	115
312	SEG<19>	5378.5	748.1	17.5	115
313	SEG<20>	5347.5	748.1	17.5	115
314	SEG<21>	5316.5	748.1	17.5	115
315	SEG<22>	5285.5	748.1	17.5	115
316	SEG<23>	5254.5	748.1	17.5	115
317	SEG<24>	5223.5	748.1	17.5	115
318	SEG<25>	5192.5	748.1	17.5	115
319	SEG<26>	5161.5	748.1	17.5	115
320	SEG<27>	5130.5	748.1	17.5	115
321	SEG<28>	5099.5	748.1	17.5	115
322	SEG<29>	5068.5	748.1	17.5	115
323	SEG<30>	5037.5	748.1	17.5	115
324	SEG<31>	5006.5	748.1	17.5	115
325	SEG<32>	4975.5	748.1	17.5	115
326	SEG<33>	4944.5	748.1	17.5	115
327	SEG<34>	4913.5	748.1	17.5	115
328	SEG<35>	4882.5	748.1	17.5	115
329	SEG<36>	4851.5	748.1	17.5	115
330	SEG<37>	4820.5	748.1	17.5	115
331	SEG<38>	4789.5	748.1	17.5	115
332	SEG<39>	4758.5	748.1	17.5	115
333	SEG<40>	4727.5	748.1	17.5	115
334	SEG<41>	4696.5	748.1	17.5	115
335	SEG<42>	4665.5	748.1	17.5	115
336	SEG<43>	4634.5	748.1	17.5	115
337	SEG<44>	4603.5	748.1	17.5	115
338	SEG<45>	4572.5	748.1	17.5	115
339	SEG<46>	4541.5	748.1	17.5	115
340	SEG<47>	4510.5	748.1	17.5	115
341	SEG<48>	4479.5	748.1	17.5	115
342	SEG<49>	4448.5	748.1	17.5	115
343	SEG<50>	4417.5	748.1	17.5	115
344	SEG<51>	4386.5	748.1	17.5	115
345	SEG<52>	4355.5	748.1	17.5	115
346	SEG<53>	4324.5	748.1	17.5	115
347	SEG<54>	4293.5	748.1	17.5	115
348	SEG<55>	4262.5	748.1	17.5	115
349	SEG<56>	4231.5	748.1	17.5	115
350	SEG<57>	4200.5	748.1	17.5	115
351	SEG<58>	4169.5	748.1	17.5	115
352	SEG<59>	4138.5	748.1	17.5	115

TRAY INFORMATION



REVISION HISTORY

Revision	Contents	Date
0.6	First Release	Jun. 2, 2006
0.7	(1) Some ESD data are corrected. (Section "ESD Consideration", page 53) (2) An I_{SB} entry is added for standby current. (Section "Specifications" – DC Characteristics, page 55)	Jun. 15, 2006
1.0	(1) LCD V_{OP} is adjusted: 6.4V~18V → 6.15V~18V (Section "Feature Highlights", page 1) (2) The recommended capacitor C_S is defined: 150~220nF / 25V. C_B is adjusted: 2.2μF/2V → 2.2μF/5V (Section "Pin Description", page 4: "Hi-V Generator Reference Circuit", page 31) (3) "When Mux rate is under 33, ..." → under 40 (Section "Command Description" – (29) Set Partial Display End, page 23) (4) "... with $V_{DD2/3} \geq 2.7V$ " → $\geq 2.8V$ (Section "LCD Voltage Setting" – Load Driving Strength for COG, page 29) (5) V_{LCD} formula is updated. (Section "V _{LCD} Quick Reference", page 30) (6) "Frame rate 231 Hz" → "Line rate 37.0 Kbps" (Section "LCD Display Controls" – Clock & Timing Generator, page 32) (7) The description of 64K color is updated. (Section "LCD Display Controls" – Input Color Formats, page 33) (8) For S8uc interface, the description is updated. (Section "Host Interface" – Serial Interface, page 38) (9) One paragraph on MTP-READ is removed. (Section "MTP NV Memory", page 47) (10) V_{LCD} for Program / Erase / Read are adjusted: 12.3V / 12.3V / 6.4V → 12.15V / 12.15V / 6.15V (11) External input for Program, TST4, is adjusted : 8.5V → 10V (12) A note on $V_{DD2/3}$ is added. (Section "MTP Operation for LCM Makers", Pp 48~51) (13) Some data are corrected. (Section "ESD Consideration", page 53) (14) The typical value of COM output impedance, $R_{ON(COM)}$: 750 → 850 Ω The typical value of SEG output impedance, $R_{ON(SEG)}$: 750 → 950 Ω The condition for $R_{ON(COM)}$ & $R_{ON(SEG)}$: $V_{LCD} = 15V$ → 16.5V (Section "Specifications" – DC Characteristics, page 55) (15) The maximum power consumption present. (Section "Power Consumption", page 55) (16) Some more AC timings are provided. (Section "AC Characteristics", Pp 56~60)	Aug. 21, 2006
1.1	(1) The S9 mode is added. (Overall, pages 1, 4, 5, 6, 36, 38, 42, 47, 62)	Oct. 2, 2006
1.2	(1) The V_{LCD} Generation sub-section is enriched by adding a diagram. (Section "V _{LCD} Voltage Setting", page 32)	Mar. 25, 2008
1.21	(1) The description of the Read Data command is enriched. (Section "Command Description" – (2) Read Data, page 9) (2) The description on Reset is updated. (Section "Reset & Power Management", Pp 49~51)	Aug. 7, 2008
1.3	$V_{DD}, V_{DD2/3}$ (Max.) : 3.3V → 3.465V (Section "Specifications" – DC Characteristics, page 59)	Mar. 31, 2009

Revision	Contents	Date
1.31	(1) The reference circuit drawings for the S8uc and S9 modes are corrected. (Pp 42~43) (2) Rising time (tr) and falling time (tf), 15nS each, are added into System Cycle Time. (Pp 58~62)	Nov. 19, 2009
1.32	Bump Height: 15uM → 12uM	Jun. 14, 2010
1.33	Bump Height: 12uM → 15uM	Aug. 5, 2010
1.34	VMTP1 (MTP-Program, MTP-Erase): 00h (6.15V) → 16h (6.4V) VMTP2 (MTP-Read): 00h (12.15V) → 26h (13V) VMTP3 (MTP Write Timer): 50h (100mS) → 66h (200mS)	Jun. 14, 2011
1.35	Provide one more Part Number for products of Bump Height 12uM.	Aug. 19, 2011
1.4	Support Black-and-white display.	Feb. 13, 2012
1.5	(1) Absolute Maximum range for Operating Temperature (Minimum): -30°C → -40°C (2) VLCD for operating at -40°C: 17.5V	Jan. 17, 2014
1.6	(1) Pad coordinates and alignment mark coordinates are updated. (2) The Recommended COG Layout drawing is updated accordingly.	Mar. 9, 2016
1.7	(1) Pad coordinates for version C are added while the ones for version B are replaced with the ones for version A. (2) The part numbers for version C are added while the ones for version B are removed. (3) Number of dummy pins is updated accordingly. (4) The COG layout drawing for version A is added. (5) The bump view drawing for version C is added accordingly as well.	Jun. 21, 2016